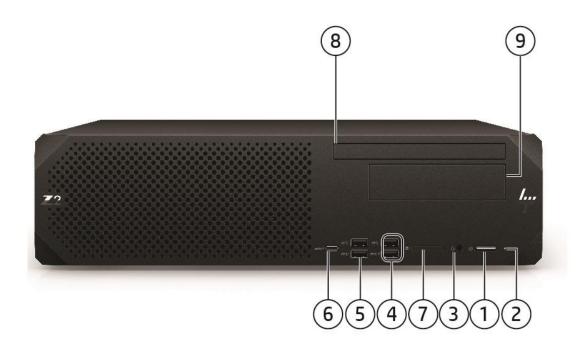
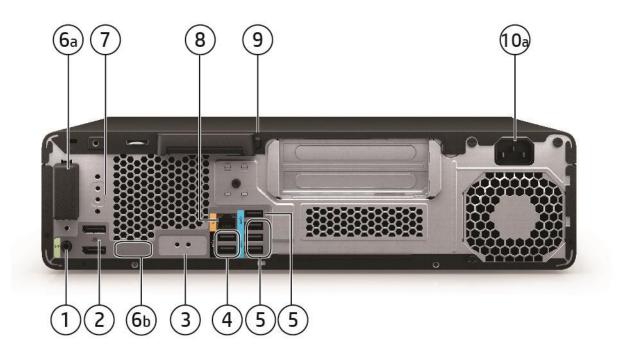
HP Z2 G9 SFF Workstation Desktop PC



Front View

- 1. Power button
- 2. HDD Activity LED & Power button LED
- 3. Universal audio jack (with CTIA & OMTP headset support)
- 4. (2) USB-A 10Gbps port (1 charge port supports up to 5V/2.1A)
- 5. (2) USB-A 10Gbps port
- 6. (1) USB-C[®] 20Gbps port (charge supports up to 5V/3A)
- 7. Media Card Reader 4.0 (optional)
- 8. Slim ODD bay
- 9. Shared internal/external 3.5" bay

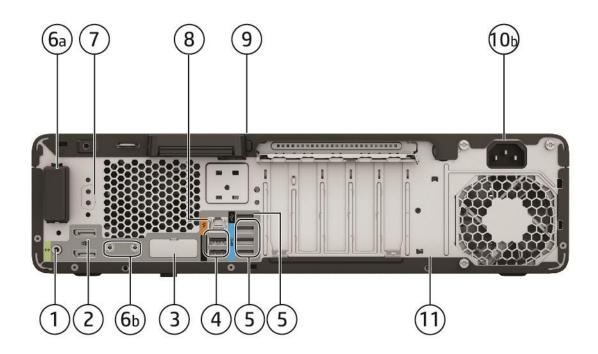


Rear View (Full Height Graphics Enabled Chassis)

- 1. Audio line out
- 2. (2) DisplayPort 1.4 ports
- 3. Flex I/O module: choose one from the following:
 (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, 1 Dual USB-A
 5Gbps, 1 USB-C® 10Gbps (Power Delivery 15W, Alt Mode
 DisplayPort), (1) 2nd 1GbE LAN, (1) 1Gbps Fiber LC LAN, (1)
 Thunderbolt 3 with USB4 Type-C® 40Gbps port (cabled to
 PCIe AIC)
- 5. (3) USB-A 5Gbps ports (1) USB-A 480Mbps port
- 6. WLAN Antenna (optional)
 - a. Internal
 - b. External
- 7. 2nd serial port (optional)
- 8. (1) 1GbE LAN
- 9. Release latch
- 10. Power connector

4. (2) USBA 480Mbps ports

NOTE: Onboard display support DP1.4/HBR2. Flex I/O module display support DP1.4/HBR3. All resolutions support up to 5120x3200 24bpp @60Hz.



Rear View (Standard Chassis) - shown with rear jet black back cover option

- 1. Audio line out
- 2. (2) DisplayPort 1.4 ports
- 3. Flex I/O module: choose one from the following:
 (1) DisplayPort 1.4, (1) HDMI 2.0b, (1) VGA, (1) Dual USB-A
 5Gbps port, (1) USB-C® 10Gbps port (Power Delivery 15W,
 Alt Mode DisplayPort), (1) 2nd 1GbE LAN, (1) 1Gbps Fiber LC
 LAN, (1) Thunderbolt 3** USB4 Type-C® 40Gbps port
 (cabled to PCIe AIC)
- 4. (2) USB-B 480Mbps ports

- 5. (3) USB-A 5Gbps ports (1) USB-A 480Mbps port
- 6. WLAN Antenna (optional)
 - a. Internal
 - b. External
- 7. 2nd serial port (optional)
- 8. (1) 1GbE LAN
- 9. Release latch
- 10. Power connector
- 11. Rear jet black GS Mark Cover option (Not shown on the image)

NOTE: Onboard Display support DP1.4/HBR2. Flex I/O module Display support DP1.4/HBR3. Resolution all support up to 5120x3200 24bpp @60Hz.

**Thunderbolt only supported on PCI-E slot3

Form Factor

Small Form Factor

Base Unit Options

Standard Half Height Graphics Base Unit Full Height Graphics Base Unit

Operating Systems

Preinstalled:

- Windows 11 Pro HP recommends Windows 11 Pro²
- Windows 11 Home HP recommends Windows 11 Pro²
- Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3
- Linux®-ready⁵
- Ubuntu^{®4,5}
 - o Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
 - Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

Web-supported only:

Windows 10 Enterprise 64²

Supported Version:

- HP tested Windows 10, versions 20H2, 21H1 and 21H2 on this platform. For testing information on newer versions of Windows 10, please see: https://support.hp.com/document/c05195282.
- Red Hat® Enterprise Linux® Workstation 85
- SUSE Linux® Enterprise Desktop 15⁵
- Ubuntu^{®4,5}
 - Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
 - Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS

¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).

² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.

³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.

⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply, and additional requirements may apply over time for updates.

⁵For detailed Linux[®] OS/hardware support information, see:

http://www.hp.com/support/linux_hardware_matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

Processors Overview^{1,2,3,4,5}



Overview

Intel 13th Generation Processors:

Intel® Core™ i5-13400 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.3GHz E-Core Max Turbo frequency, up to 4.6 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)

Intel® Core™ i5-13500 (2.5GHz P-Core base frequency, 1.8GHz E-Core base frequency, up to 3.5GHz E-Core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-13600 (2.7GHz P-Core base frequency, 2GHz E-Core base frequency, up to 3.7GHz E-Core Max Turbo frequency, up to 5 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i5-13600K (3.5GHz P-Core base frequency, 2.6GHz E-Core base frequency, up to 3.9GHz E-Core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 24MB L3 cache, 6 P-cores and 8 E-cores, 20 threads)

Intel® Core™ i7-13700 (2.1GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.1Ghz E-Core base frequency, up to 5.1Ghz E-Core base frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i7-13700K (3.4GHz P-Core base frequency, 2.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.3 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i9-13900 (2GHz P-Core base frequency, 1.5GHz E-Core base frequency, up to 4.2GHz E-Core Max Turbo frequency, up to 5.2 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel® Core™ i9-13900K (3GHz P-Core base frequency, 2.2GHz E-Core base frequency, up to 4.3GHz E-Core Max Turbo frequency, up to 5.4 GHz P-core Max Turbo frequency, 36MB L3 cache, 8 P-cores and 16 E-cores, 32 threads)

Intel 12th Generation Processors:

Intel® Core™ i9-12900K (2.4GHz E-core base frequency, 3.2GHz P-core base frequency, up to 3.9 GHz E-core Max Turbo frequency, up to 5.1 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i9-12900 (1.8GHz E-core base frequency, 5.0 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo frequency, up to 5.0 GHz P-core Max Turbo frequency, 30MB L3 cache, 8 P-cores and 8 E-cores, 24 threads)

Intel® Core™ i7-12700K (2.7 GHz E-core base frequency, 3.6 GHz P-core base frequency, up to 3.8 GHz E-core Max Turbo frequency, up to 4.9 GHz P-core Max Turbo frequency, 25MB L3 cache, 8 P-cores and 4 E-cores, 20 threads)

Intel® Core™ i7-12700 (1.6 GHz E-core base frequency, 2.1 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo frequency, up to 4.8 GHz P-core Max Turbo frequency, 25MB L3 cache, 8 P-cores and 4 E-cores, 20 threads)

Intel® Core™ i5-12600K (2.8 GHz E-core base frequency, 3.7 GHz P-core base frequency, up to 3.6 GHz E-core Max Turbo frequency, up to 4.9 GHz P-core Max Turbo frequency, 20MB L3 cache, 6 P-cores and 4 E-cores, 16 threads)

Intel® Core™ i5-12600 (3.3 GHz P-core base frequency, up to 4.8 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0 E-cores, 12 threads)

Intel® Core™ i5-12500 (3.0 GHz P-core base frequency, up to 4.6 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0-E-cores, 12 threads)

Intel® Core™ i5-12400 (2.5 GHz P-core base frequency, up to 4.4 GHz P-core Max Turbo frequency, 18MB L3 cache, 6 P-cores and 0-E cores, 12 threads)

Intel® Core™ i3-12300 (3.5 GHz P-core base frequency, up to 4.4 GHz P-core Max Turbo frequency, 12MB, 4 P-cores. 8 threads)

Intel® Core™ i3-12100 (3.3 GHz P-core base frequency, up to 4.3 GHz P-core Max Turbo frequency, 12MB, 4 P-cores. 8 threads)

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

² Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

³ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro



Overview

⁴Memory will run at 4400 speed (MT/s) if there is one DIMM per channel. 2 DIMMS per channel will run 4000 speed (MT/s). DIMMs must be the same, either 8GB or 16GB DIMMs. 32GB DIMMs run at 3200 MT/s.

Color Black

Convertibility The SFF can either be placed flat on the desktop or made to stand on the desk with the optional tower

stand.

Expansion Slots

(see system board section

for more details)1

Standard Base Unit with Half Height PCIe	Full Height Graphics PCIe Base Unit
Slot 1: PCIe Gen4 x16	Slot 1: PCIe Gen4 x16 ¹
Slot 2: PCIe Gen3 x4	Slot 2: PCIe Gen4 x8 (with x16 connector) ¹
Slot 3: PCIe Gen3 x4 - with x16 Connector	
Slot 4:PCIe Gen3 x1	¹ When slot 2 is configured with a PCIe card,
	slot 1 will automatically downgrade to PCIe
	x8 electrical

Expansion Bays (see

storage section for more

details)

(1) Shared internal/external 3.5" bay

NOTE: This shared bay is supported only with Core i7 / i9 processors.

(1) Internal 3.5" bay

(1) Internal 3.5" bay (optional in Standard SFF. Not Available with Full Height Graphics Base Unit)

(1) Dedicated 9.5mm slim optical disk drive bay

Front I/O 2 Type-A SuperSpeed USB 10Gbps signaling rate port (1 charge port supports up to 5V/2.1A), 2 Type-A

SuperSpeed USB 10Gbps signaling rate port, 1 Type-C SuperSpeed® USB 20Gbps signaling rate port

(charge supports up to 5V/3A). 1 SD card reader (optional). 1 universal audio jack

Internal I/O (1) USB 480Mbps header for SD card reader

> (1) serial port available with header (1) serial and PS/2 available with header

Rear I/O (2) DisplayPort 1.4 [3], (1) Audio Line out, (1) 1GbE LAN, (3) USB-A 480Mbps ports, (3) USBA 5Gbps

ports, (1) serial (optional), (1) Flex I/O port (VGA, HDMI 2.0b, DisplayPort 1.4, USB-C® 10Gbps port (Power Delivery 15W, Alt Mode Display Port), Dual USB-A 5Gbps port, 2nd 1GbE LAN, (1) Thunderbolt 3

with USB4 Type-C® 40Gbps (cabled to PCIe AIC), (1) 1Gbps Fiber LC NIC

Optional I/O Flex IO* – choose one of the following options: (1) DisplayPort™ 1.4, (1) HDMI 2.0b, (1) VGA, (1) 2nd

> 1GbE LAN, (1) 1Gbps Fiber LC NIC, (1) Dual USB-A 5Gbps port,(1) USB) ® 10Gbps port (15W USB Power Delivery, Alt Mode DisplayPort™), (1) Thunderbolt™ 3 with USB4 Type-C® 40Gbps port (cabled to

PCIe® AIC); Front – (1) SD card reader; Rear – (1) serial; (1) SD 4.0 card reader

* Flex IO port and one PCIe slot will be occupied when Thunderbolt is installed.

Thunderbolt will be available in Q2, 2022 (1st refresh).

Interfaces Supported

SD card reader (optional)

On-board RAID Support

SATA and NVME RAID 0 Striped Array

SATA RAID and NVME RAID 1 Mirror Array

Chassis Dimensions

(H x W x D)

H: 3.95" [100mm] W: 15.1" [384mm]

D: 12.1" [308mm] (Standard desktop orientation)

Packaged Dimensions H: 20.4" (514mm)

> W: 7.83" (199mm) D: 19.29" (490mm)

Exact weights depend upon configuration (System weight only). Weight

Starting at 5.0kg (11.1lbs.)



⁵ Error Correction Memory

Overview

Temperature Operating: 5° to 35° C (40° to 95° F)

Above 1524 m (5,000 feet) altitude, the maximum operating temperature is reduced by 1° C (1.8° F) for

every 305 m (1,000 feet) increase in elevation Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude (non-

pressurized)

Operating (with Rotational Hard Drives): 3,048 m (10,000 feet) Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Temperature for details.

Power Supply 260W PSU: only available with standard half height graphics base unit

260W wide-ranging, active Power Factor Correction, 92% Efficiency.

LiteOn 260W PSU Efficiency Report Chicony 260W PSU Efficiency Report AcBel 260W PSU Efficiency Report

450W PSU: only available with standard half height graphics base unit 450W wide-ranging, active Power Factor Correction, 90% Efficiency.

https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

LiteOn 450W PSU Efficiency Report

550W PSU: only available with full height graphics base unit 550W wide-ranging, active Power Factor Correction, 92% Efficiency.

LiteOn550W PSU Efficiency Report AcBel 550W PSU Efficiency Report

Backup Devices For a complete listing of compatible DAT tape drives, LTO tape drives and RDX Removable Disk Backup

System offerings, please visit http://www.hp.com/go/connect

Chipset Intel® W680 chipset

Memory 4 DIMM slots, supporting up to 128GB ECC/non-ECC, DDR5 unbuffered DIMM memory. Speed

depending on the system configuration. See Supported Components / Memory Section for details.



Supported Components

Storage / Hard Drives*		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	SATA Hard Drives ¹				
	500GB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ036AA	1
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	LQ037AA	1
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD	Υ	Υ	QB576AA	1
	1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	WOR10AA	1
	2TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	2Z274AA	1
	4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	K4T76AA	1
	8TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)	Υ	Υ	2Z273AA	1
	12TB 7200 RPM SATA-6G 3.5in Enterprise HDD	Υ	Υ	5S461AA	1
	500GB SATA 7.2K SED SFF HDD	Υ	Υ	D8N29AA	1
	PCIe Solid State Drives				
	HP ZTurbo 512GB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201G0AA	
	HP ZTurbo 512GB PCIe-Gen 4x4 SED Z2 SSDKit	Υ	Υ	201F9AA	
	HP ZTurbo 1TB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201F5AA	
	HP ZTurbo 2TB PCIe-Gen 4x4 TLC Z2 SSDKit	Υ	Υ	201F8AA	
	HP Z Turbo Drive 1TB 2280 PCIe-4x4 SED 0PAL2 TLC Z2 Kit SSD	Υ	Υ	223A3AA	
	HP Z Turbo Drive 2TB 2280 PCIe-4x4 SED 0PAL2 TLC Z2 Kit SSD	Υ	Υ	223A4AA	
	Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 Z2 Kit SSD	Υ	Υ	5S498AA	
	HP 256GB PCIe NVME TLC M.2 Z2 G9 TWR/SFF SSD	Υ	Υ		
	HP 500GB PCIe NVME TLC M.2 Z2 G9 TWR/SFF SSD	Υ	Υ		
	HP 1TB PCIe NVME TLC M.2 Z2 G9 TWR/SFF SSD	Υ	Υ		
	HP 256GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z1AA	
	HP 512GB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z2AA	
	HP 1TB 2280 PCIe-4x4 NVMe Value M.2 Z2 Kit SSD	Υ	Υ	4M9Z3AA	
	HP Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 Z2 Kit SSD	Υ	Υ	5S492AA	
	HP Z Turbo 2TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T75AA	
	HP Z Turbo 1TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T76AA	
	HP Z Turbo 1TB PCIe-4x4 TLC SSD Module	Υ	Υ	38T77AA	
	HP Z Turbo 2TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T79AA	
	HP Z Turbo 512GB PCIe-4x4 TLC SSD Module	Υ	Υ	38T80AA	
	HP Z Turbo 512GB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	38T81AA	
	HP Z Turbo 4TB 2280 PCIe-4x4 TLC M.2 SSD Module	Υ	Υ	5S496AA	
	HP Z Turbo 4TB 2280 PCIe-4x4 SED OPAL2 TLC M.2 SSD Module	Υ	Υ	5S497AA	

NOTE 1: HDD option kits also require purchase of separate cable kit (available Sept 2022). This option kit includes necessary components to install the HDD options in an internal or external bay. **HP Z2 SFF HDD Cable Kit 6Z9U5AA.** This is only needed when HDD is purchased as AMO.



Supported Components

*For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Graphics		Factory Configured	Option Kit	Option Kit Part Number	Supported # of cards	
	Graphics Cable Adapters					
	HP DisplayPort To HDMI True 4k Adapter	Υ	Υ	2JA63AA		
	HP Single miniDP-to-DP Adapter Cable	Υ	Υ	2MY05AA		
	HP DisplayPort To DVI-D Adapter	Υ	Υ	FH973AA/A6		
	HP DisplayPort To VGA Adapter	Υ	Υ	AS615AA/AT		
	HP DisplayPort To VGA Adapter	Υ	Υ	AS615A6		
	HP DisplayPort To VGA Adapter	Υ	Υ	F7W97AA		
	HP USB-C to DisplayPort Adapter	Υ	Υ	4SH08AA		
	HP USB-C to HDMI Adapter	Υ	Υ	4SH07AA		
	HP USB-C to VGA Adapter	Υ	Υ	4SH06AA		
	Entry 3D Graphics					
	NVIDIA® T400 2 GB Graphics	Υ	Υ	340K8AA	2	1
	NVIDIA® T400 4 GB Graphics	Υ	Υ	5Z7E0AA/AT	2	
	NVIDIA® T600 4 GB Graphics	Υ	Υ	340K9AA	2	1
	AMD Radeon RX 6400 4 GB DH DP+HDMI Graphics	Υ	Υ	6Q3U4AA	1	
	AMD Radeon Pro WX 3200 4GB (4)mDP GFX, w/2 mDP-to-DP adapters	Υ	Υ	6YT68AA	1	
	Mid-range 3D Graphics					
	NVIDIA® T1000 4 GB Graphics	Υ	Υ		2	
	NVIDIA® T1000 8 GB Graphics	Υ	Υ	5Z7D8AA/AT	2	
	NVIDIA Long-Life T1000E 8 GB 4mDP Graphics	Υ	Υ	6V9V4AA/AT	2	
	NVIDIA® RTX™ A2000 6 GB 4mDP Graphics	Υ	Υ	340L0AA	1	3
	NVIDIA® RTX™ A2000 12GB Graphics*	Υ	Υ	5Z7D9AA/AT	1	3
	NVIDIA Long-Life RTX A2000E 12 GB 4mDP Graphics	Υ	Υ	6V9V5AA/AT	1	
	AMD Radeon™ Pro W6600 Graphics (8GB GDDR6 dedicated) *	Υ	Υ	340K5AA	1	
	High-end 3D Graphics					
	AMD Radeon™ RX 6700 XT Graphics (12 GB GDDR6 dedicated) *	Υ	N		1	2
	NVIDIA® RTX™ A4000 16 GB Graphics*	Υ	Υ	20X24AA/AT	1	2, 3
	NVIDIA Long-Life RTX A4000E 16 GB 4DP Graphics	Υ	Υ	6H7J7AA	1	2, 3

Note 1: NVIDIA® T400 (2 GB GDDR6 dedicated) and NVIDIA® T600 (4 GB GDDR6 dedicated) may go End of Life in late 2022.

Note 2: Full Height Graphics (eg. NV A4000, AMD 6700) are only supported by Full Height Chassis/550W PSU)

Note 3: Double wide card consumes 2 PCIe slots



Supported Components

Memory		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP 8GB (1x8GB) DDR5-4800 UDIMM NECC	Υ	Υ	4M9X9AA	2, 3
	HP 16GB (1x16GB) DDR5-4800 UDIMM NECC	Υ	Υ	4M9Y0AA	2, 3
	HP 16GB (1x16GB) DDR5-4800 UDIMM ECC	Υ	Υ	4M9Y1AA	1,2,3
	HP 32GB (1x32GB) DDR5-4800 UDIMM NECC	Υ	Υ	4M9Y2AA	2, 3
	HP 32GB (1x32GB) DDR5- 4800 UDIMM ECC	Υ	Υ	4M9Y3AA	1, 2, ,3

NOTE 1: See Processor Overview section for processors that support ECC Memory.

NOTE 2: Two channels of DDR5 memory are supported. To realize full performance one DIMM must be inserted into each channel.

NOTE 3: Though the memory modules can run up to 4800MHz, the current platform will support the maximum memory speed of 4400MHz.

The system speed will be determined by these key factors:

Module Configuration	Description of configuration	Max Memory Speed (Actual Memory speed is dependent on CPU)
Single 8, 16 or 32GB DIMM per channel	Configurations that contain only one or two DIMM modules with DIMMs only in the black slots	4400MHz
Two 8 or 16GB DIMMs in a channel	Configurations with 3 or 4 DIMMs installed in a system. Memory DIMMs must all be of the same size.	4000MHz
Two 32GB DIMMs in a channel	Configurations with 3 or 4 32GB DIMMs installed in a system	3600MHz

Optical and Removable Storage		Factory Configured	Option Kit	Option Kit Part Number	Support Notes
	HP DP25 Removable 2.5" HDD Frame/Carrier	N	Υ	W3J84AA	
	HP DP25 2.5 in HDD Spare Carrier	N	Υ	W3J85AA	
	HP Z2 SFF DVD-Writer 9.5mm Slim ODD	Υ	Υ	4L5J9AA	1
	HP Z2 SFF DVD-ROM 9.5mm Slim ODD	Υ	Υ	4L5J8AA	1
	HP CRU QX118 3.5 in Front Removable Frame/Carrier	Υ	N		
	HP CRU QX328 3.5 in Front Removable Frame/Carrier	Υ	Υ	4N012AA	2, 3
	HP CRU Secure High Performance Storage Module with 2TB M.2 SSD	Υ	Υ	56Q87AA	4
	HP CRU Secure High Performance Storage Module with 1TB M.2 SSD	Υ	Υ	56Q88AA	4
	HP CRU Secure High Performance Storage Module	Υ	Υ	56Q89AA	4

NOTE 1: Duplication of copyrighted material is strictly prohibited. Actual speeds may vary. Double Layer media compatibility will widely vary with some home DVD players and DVD-ROM drives. Note that DVD-RAM cannot read or write to 2.6GB Single Sided/5.2 Double Sided-Version 1.0 Media.

NOTE 2: HP CRU QX328 3.5 in Front Removable Frame/Carrier is only compatible with Intel core i7 and core i9 processors

NOTE 3: Requires separate purchase of HP CRU SHIP Storage Module(s).

with 512GB M.2 SSD



Supported Components

NOTE 4: HP CRU Secure High Performance Storage (SHIPS) Module Kit contains select M.2 SSD for install into a factory configured or after market option front removeable storage carrier (HP CRU QX328 Frame/Carrier).

Networking and Communications		Factory Configured	Option Kit	Option Kit Part Support No Number	otes
	Integrated Intel® I219LM PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.0)	Υ	N	2	
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT 3	
	HP Flex 1GbE Fiber LC Single Port	Υ	Υ	20J15AA 3	
	Intel Ethernet I350-T4 4-Port 1Gb NIC*	N	Υ	W8X25AA 3	
	Intel X550 10GBASE-T Dual Port NIC	Υ	Υ	1QL46AA	
	Intel Ethernet Network Adapter I225-T1	Υ	Υ	406L9AA	
	Intel Wi-Fi 6E AX211 BT 5.3 wireless card M.2 non- vPro ^{1,**}	Υ	N	1	
	Allied Telesis AT-2911T/2-901 Dual Port 1GbE NIC	Υ	Υ	6E3Y9AA/AT	
	NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC	Υ	Υ	436M8AA	
	HP 10GbE SFP+ SR/SW LC Fiber Optic Transceiver	Υ	Υ	860T8AA	
	HP 25GbE SFP28 LC Fiber Optic Transceiver	Υ	Υ	860T9AA	

^{*}Intel I350-T4 4-port GbE NIC is an After Market Option only.

NOTE 1: Intel AX211 with external antenna support WIFI 6E. Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available in countries where Wi-Fi 6E is supported. The integrated network connection is required to support Intel® vPro® Technology.

NOTE 2: If AMT is provisioned, then network teaming with the integrated LAN port is not possible. **NOTE 3**: "Gigabit" Ethernet indicates compliance with IEEE standard 802.3ab for Gigabit Ethernet, and does not connote actual operating speed of 1 Gb/sec. For high speed transmission, connection to a Gigabit Ethernet server and network infrastructure is required

Racking and Physical Security		Factory Configured	Option Kit	Option Kit Part Number
	HP Keyed Cable Lock	N	Υ	T1A62AA
	HP Master Keyed Cable Lock 10mm	N	Υ	T1A63AA
	HP Business PC Security Lock V3 Kit	N	Υ	3XJ17AA

Input Devices		Factory		
-		Configur ed	Option Kit	Option Kit Part Number
	HP 320K Wired Keyboard	Υ	Υ	9SR37AA
	HP 455 Programmable Wireless Keyboard	Υ	Υ	4R177AA
	HP 975 USB+BT Dual-Mode Wireless Keyboard	Υ	Υ	3Z726AA
	HP 655 Wireless Keyboard and Mouse Combo	Υ	Υ	4R009AA



^{**}Intel AX211 must be configured at time of purchase. Not available as an After Market Option.

Supported Components

ns Eactory		Λ.	ntion Kit Dart
HyperX SoloCast - USB Microphone (Black) (HMIS1X-XX-BK/G)	N	Υ	4P5P8AA
HyperX Cloud Stinger Core GAM HEADSET PC	N	Υ	4P4F4AA
HyperX Cloud Flight - Wireless Gaming Headset (Black-Red) (HX-HSCF-BK/AM)	N	Υ	4P5L4AA
HyperX Cloud Core BLK GAM HEADSET	N	Υ	4P4F2AA
HyperX Cloud MIX Wireless GAM HEADSET	N	Υ	4P5K9AA
HyperX Pulsefire Core - Gaming Mouse	N	Υ	4P4F8AA
HyperX Pulsefire Haste White Wireless Gaming Mouse 2	N	Υ	6N0A9AA
HyperX Pulsefire Haste Black Wireless Gaming Mouse 2	N	Υ	6N0B0AA
HP Creator 935 Black Wireless Mouse	Υ	Υ	1D0K8AA
HP 125 Wired Mouse	Υ	Υ	265A9AA
HP 128 Laser Wired Mouse	Υ	Υ	265D9AA
HP Wired 320M Mouse	Υ	Υ	9VA80AA
HyperX Alloy MKW100 - Mechanical Gaming Keyboard	N	Υ	4P5E1AA
HP Wired Desktop 320MK Mouse and Keyboard	Υ	Υ	9SR36AA
HP 125 Wired Keyboard	Υ	Υ	266C9AA

Flexport Options		Factory Configured	Option Kit	Option Kit Part Number
	HP DP Flex Port 2020	Υ	Υ	141J7AA/AT
	HP 1GbE LAN Flex Port 2020	Υ	Υ	141J6AA/AT
	HP Flex 1GbE Fiber LC Single Port	Υ	Υ	20J15AA
	HP Dual USB-A 3.2 Gen1 Flex 2020	Υ	Υ	141J8AA/AT
	HP HDMI Flex Port	Υ	Υ	69D47AA/AT
	HP USB-C 3.2 Gen2 Alt Flex Port 2020	Υ	Υ	141K6AA/AT
	HP VGA Flex Port 2020	Υ	Υ	141K7AA/AT

Miscellaneous		Factory Configured	Option Kit	Option Kit Part Number
	HP Z2 Internal Serial Port and PS/2 Port	Υ	Υ	141K9AA/AT
	HP Z2 Power Cord Kit	Υ	Υ	1N1D5AA
	HP Z2 2nd serial port adapter	Υ	Υ	141K8AA/AT
	HP PCIe x1 Parallel Port Card	Υ	Υ	N1M40AA
	HP Z2 SFF Dust Filter	Υ	Υ	4N002AA
	HP Z2 SFF Dust Filter and Bezel	Υ	Υ	4N003AA
	HP Z2 SFF HDD Cable Kit	N	Υ	6Z9U5AA
	HP Anyware Integrated Remote System Controller	Υ	Υ	7K6D9AA
	HP Anyware Remote System Controller Main Board Adapter	Υ	Υ	7K6D8AA
	HP Anyware Remote System Controller	Υ	Υ	7K6D7AA
	HP Anyware Remote System Controller for Universal KVM	N	Υ	7K7N2AA

Software		Factory Configured	Option Kit	Support Notes
	HP Performance Advisor	Υ	N	1
	HP PC Hardware Diagnostics UEFI (Windows OS only)	Υ	N	2
	HP PC Hardware Diagnostics Windows		N	3
	HP Wolf Security	Υ	N	
	HP Notifications	Υ	N	



Supported Components

HP Desktop Support Utility	Υ	N	
HP Documentation	Υ	N	
HP Image Assistant	N	N	
HP Support Assistant	N	N	
myHP	Υ	N	
HP Easy Clean	Υ	N	
Kingsoft WPS Office	Υ	N	4
My Office	Υ	N	5
Adobe Substance 3D Collection Plan	N	Υ	6
WSL2/Ubuntu Data Science Stack	Υ	N	7

Note 1: Supports, and preinstalled with Windows 10 only. Also available as a free download from

http://www.hp.com/go/performanceadvisor

Note 2: Windows OS only

Note 3: Not available in Russia

Note 4: Only available in China

Note 5: Only available in Russia

Note 6: Not available in China

Note 7: Optional Software

Supported Components

Operating Systems

Windows 11 Pro - HP recommends Windows 11 Pro²

Windows 11 Home - HP recommends Windows 11 Pro²

Windows 10 Pro (available through downgrade rights from Windows 11 Pro) 1,2,3

Linux®-ready5

Ubuntu®4,5

- o Intel 12th generation processors will support and preinstall Ubuntu 20.02 and 20.04.
- Intel 13th generation processors support and preinstall Ubuntu 22.04 LTS
- ¹ Device comes with Windows 10 and a free Windows 11 upgrade or may be preloaded with Windows 11. Upgrade timing may vary by device. Features and app availability may vary by region. Certain features require specific hardware (see Windows 11 Specifications).
- ² Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows is automatically updated and enabled. High speed internet and Microsoft account required. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com.
- ³This system is preinstalled with Windows 10 Pro software and also comes with a license for Windows 11 Pro software and provision for recovery software. You may only use one version of the Windows software at a time. Switching between versions will require you to uninstall one version and install the other version. You must back up all data (files, photos, etc.) before uninstalling and installing operating systems to avoid loss of your data.
- ⁴ Not all features are available in all editions or versions of Ubuntu. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS to take full advantage of Ubuntu functionality. Ubuntu may be automatically updated. ISP fees may apply and additional requirements may apply over time for updates.

⁵For detailed Linux® OS/hardware support information, see:

http://www.hp.com/support/linux hardware matrix

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows® 8 or Windows 7 operating system on products configured with Intel® and AMD® 7th generation and forward processors or provide any Windows® 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282



Supported Components

HP BIOS

Key features of the HP BIOS include:

- Deployment and manageability HP BIOS provides several technologies that help integrate the HP Z2 G9 SFF Workstation Desktop PC into the enterprise, such as PXE, remote recovery, remote configuration, remote control, and BIOS (F10) Setup support for 15 languages.
- Network firmware updates Update your BIOS via the cloud or standardize on a BIOS version hosted on an Enterprise network.
- Stability HP BIOS supports the HP stable product roadmap by releasing only critical BIOS changes to the factory and advanced change notification.
- Class 3 UEFI specification version 2.7
- Absolute Persistence agent For tracking and tracing services, available in select countries, separate software and purchase of a subscription is required.
- Thermal and power management The HP BIOS provides and enables thermal and power management technologies so component temperatures are managed for high reliability and to assist in operating the HP Workstation computer in any enterprise environment.
- Acoustic performance Industry leading acoustic emissions across the range of operating conditions.
- Serviceability HP BIOS provides diagnostic and detailed service information.
- Upgrades and recovery HP BIOS provides numerous ways to upgrade HP Workstation computers, including BIOS updates from within Windows (HP Firmware Update and Recovery), Capsule update, HP Client Manager, and fail-safe recovery. In addition, the HP BIOS Configuration Utility enables replication of BIOS settings within Windows while the Replicated Setup feature provides the same capability within BIOS (F10) Setup. The BIOS Configuration Utility is available from the HP support website.
- HP BIOS uses PKI signing of the BIOS for trusted BIOS upgrades and recovery.

Additional HP BIOS Features:

- Power-On password Helps prevent an unauthorized user from powering on the system.
- Administrator password Also known as the BIOS Setup password, this helps prevent unauthorized changes to the system configuration. If the administrator password is not known, the BIOS cannot be updated and changes cannot be made to BIOS settings using BIOS Setup or under the OS.
- S4/S5 Maximum Power Savings setting supports EU Lot6 requirement and allows the computer to power down below 0.5W in S4/S5 (when turned off). When S4/S5 Maximum Power Savings feature is enabled below features are turned off:
 - -Power to expansion connectors / slots
 - -Most Wake events other than power buttons and WOL (Wake on LAN supported by embedded Lan controller under S4/S5 Maximum Power Saving Enabled)
 - -USB charging ports

HP Sure Start Gen7

- BIOS Integrity checking Sure Start protection ensures that only trusted BIOS code is executed
 and not rootkits, viruses and malware. Verification is done upon boot up, shutdown and while
 the system is on.
- Sure Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability. Start is set by default to automatically repair the BIOS if corrupted or compromised but is policy driven for better manageability.
- Protecting beyond BIOS Integrity checking and repair is extended to other data that should be protected such as network configuration parameters, platform specific information (i.e. system IDs), secure boot credentials, and other code the system needs to boot.



Supported Components

 Audit enabled – System Audit via Sure Start Event Logs capture data such as incident, repair date and time for troubleshooting and investigating.

NOTE: HP Sure Start Gen7 is available on HP Workstation products equipped with Intel® 12th generation processors.

HP Performance Control Modes

HP Z Desktop Workstations offers Performance Control Modes in the F10 BIOS menu. Z2 G9 offers Quiet Mode, Performance Mode and High-Performance Mode. HP recommends using High Performance Mode unless you have concerns about acoustics in an open office environment. Customers can get up to 34% performance improvements using High Performance Mode over Performance Mode*. It is possible to configure High Performance Mode as default from the factory.

How to Set HP Performance Control Modes in HP F10 BIOS Menu

In the F10 BIOS Menu, the setting titled "Performance Control" is adjustable to High Performance Mode, Performance Mode or Quiet Mode. These modes are choice points for performance and acoustic tradeoffs based on user needs or recommended balanced conditions in performance and noise optimization.

At startup, push the F10 key while system is booting to get to the BIOS Menu.

Go to --> Advanced -> System Options ->scroll down and choose "Performance Control"

Set the Performance Mode you desire and then go back to Main->Save Changes and Exit -> Yes

The machine will restart in the mode you've chosen.

You can change these modes anytime you prefer to prioritize acoustics (Quiet Mode), want a balance between performance and acoustics (Performance Mode) or prefer to prioritize performance (High Performance Mode).

For more information on performance control modes, please see the white paper called, HP Performance Control Modes for Z Desktop Workstations.

*Compared to Performance Mode. Performance increase based on Z2 Tower G9 with 64GB of memory, 1TB NVMe, Windows 11 22H2 OS, RTX A4000, i9-13900 CPU using SPECworkstation 3.1

SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

Software

HP Support Assistant ¹⁴
HP Image Assistant
HP Desktop Support Utility
HP Documentation
HP Notifications
HP PC Hardware Diagnostics UEFI
HP PC Hardware Diagnostics Windows
HP Performance Advisor¹
myHP
HP Easy Clean²⁰
WSL/Ubuntu Data Science Stack
HP Privacy Settings
Touchpoint Customizer for Commercial



Supported Components

Manageability Features

HP Driver Packs²

HP UWP Pack

HP System Software Manager (SSM)

HP Manageability Integration Kit Gen43

HP Smart Support⁵

HP Client Catalog (download)

HP Image Assistant (download)

HP Cloud Recovery

HP Client Management Script Library (download)

HP BIOSphere Gen6 13

Client Security Software

HP Client Security Suite Gen7⁴ including: (including Credential Manager, HP Password Manager⁶, HP Spare Key)

HP Power On Authentication

Microsoft Defender⁷

Security Management

HP Secure Erase 16

HP Wolf Pro Security Edition (optional) 18

HP Wolf Security for Business²² Includes:

HP Sure Click¹¹

HP Sure Sense¹²

HP Sure Run Gen59

HP Sure Recover Gen4 10

HP Sure Start Gen78

HP Tamper Lock

HP Sure Admin 17

HP Client Security Manager Gen 74

- ¹ HP Performance Advisor Software HP Performance Advisor is ready to help you get the most out of your HP Workstation from day one—and every day after. Learn more or download at: http://hp.com/PerformanceAdvisor
- ² HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.
- ³ HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html
- ⁴ HP Client Security Manager Gen7 requires Windows and is available on the select HP PCs.
- ⁵ HP Smart Support automatically collects the telemetry necessary upon initial boot of the product to deliver device-level configuration data and health insights and is available preinstalled on select products, thru HP Factory Configuration Services; or it can be downloaded. For more information about how to enable HP Smart Support or for download, please visit http://www.hp.com/smart-support.
- ⁶ HP Password Manager requires Internet Explorer or Chrome or FireFox. Some websites and applications may not be supported. User may need to enable or allow the add-on / extension in the internet browser.
- ⁷ Microsoft Defender Opt in and internet connection required for updates.
- ⁸ HP Sure Start Gen 7 is available on select HP PCs and workstations. See product specifications for availability.
- ⁹ HP Sure Run Gen5 is available on select Windows 11 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors
- ¹⁰ HP Sure Recover Gen4 is available on select HP PCs and requires Windows 10 and an open network connection. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. Network based recovery using Wi-Fi is only available on PCs with Intel Wi-Fi Module
- 11 HP Sure Click requires Windows 10 Pro or higher or Enterprise. See https://bit.ly/2PrLT6A_SureClick for complete details.



Supported Components

¹² HP Sure Sense requires Windows 11 Pro or Enterprise and supports Microsoft Internet Explorer, Google Chrome™, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

¹³ HP BIOSphere Gen6 features may vary depending on the platform and configurations.

¹⁴ HP Support Assistant requires Windows and Internet access.

¹⁶ Secure Erase - For the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel® Optane.

¹⁷ HP Sure Admin requires Windows 11, HP BIOS, HP Manageability Integration Kit from

http://www.hp.com/go/clientmanagement and HP Sure Admin Local Access Authenticator smartphone app from the Android or Apple store.

¹⁸ HP Wolf Pro Security Edition is available preloaded on select SKUs and, depending on the HP product purchased, includes a paid 1-year or 3-year license. The HP Wolf Pro Security Edition software is licensed under the license terms of the HP Wolf Security Software - End-User license Agreement (EULA) that can be found at: https://support.hp.com/us-en/document/ish_3875769-3873014-16 as that EULA is modified by the following: "7. Term. Unless otherwise terminated earlier pursuant to the terms contained in this EULA, the license for the HP Wolf Pro Security Edition (HP Sure Sense Pro and HP Sure Click Pro) is effective upon activation and will continue for either a twelve (12) month or thirty-six (36) month license term ("Initial Term"). At the end of the Initial Term you may either (a) purchase a renewal license for the HP Wolf Pro Security Edition from HP.com, HP Sales or an HP Channel Partner, or (b) continue using the standard versions of HP Sure Click and HP Sure Sense at no additional cost with no future software updates or HP Support.

²⁰ HP Easy Clean requires Windows 10 RS3 and higher and will disable the keyboard, touchscreen, and clickpad only. Ports are not disabled. See user guide for cleaning instructions.

²² HP Wolf Security for Business requires Windows 10 or higher, includes various HP security features and is available on HP Pro, Elite, RPOS and Workstation products. See product details for included security features



System Technical Specifications

System Board

System Board Form Factor

Customized PCB 231.04 x 301.24 mm (9.213X11.86inches)

Processor Socket

Single LGA-1700

CPU Bus Speed

DMI

Chipset

Intel® PCH W680

Super I/O Controller

Nuvoton SIO21

Memory Expansion Slots 4 DDR5 memory slots

Memory Type Supported DDR5, UDIMM (Unbuffered), ECC& non-ECC

Memory Modes

Non-Interleaved for single channel. Interleaved when both channels are populated.

Memory Speed Supported 3600MT/s to 4400MT/s DDR5, dependent on memory configuration¹

¹Though the memory modules can run up to 4800MHz, the current platform will only be able to support the maximum memory speed of 4400MHz.

The system speed will be determined by a number of key factors:

Module **Description of configuration Max Memory Speed (Actual Memory** Configuration speed is dependent on CPU) Single 8, 16 or 32GB Configurations that contain only one or two 4400MHz DIMM per channel DIMM modules with DIMMs only in the black slots Configurations with 3 or 4 DIMMs installed in a Two 8 or 16GB 4000MHz DIMMs in a channel system. Memory DIMMs must all be of the same Two 32GB DIMMs in Configurations with 3 or 4 32GB DIMMs installed 3600MHz a channel in a system

Memory Protection

ECC available on data

Maximum Memory

128GB

Memory Configuration (Supported)

8GB, 16GB and 32GB non-ECC, 16GB and 32GB ECC unbuffered DIMMs are supported. ECC and non-ECC memory DIMMs cannot be mixed in the same system

NOTE: Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 11 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

PCI Express Connectors

Standard Base Unit with Half Height PCIe	Full Height Graphics PCIe Base Unit
Slot 1: PCIe Gen4 x16	Slot 1: PCIe Gen4 x16 ¹
Slot 2: PCIe Gen3 x4	Slot 2: PCIe Gen4 x8 (with x16 connector) ¹
Slot 3: PCIe Gen3 x4 - with x16 Connector	
Slot 4:PCIe Gen3 x1	¹ When slot 2 is configured with a PCIe card, slot 1
	will automatically downgrade to PCIe x8 electrical

(1) M.2 2280 Storage (PCIe Gen4 x4) (1) M.2 2280 Storage (PCIe Gen4 x4) (1) M.2 2280 Storage (PCIe Gen4 x4)

(1) M.2 2230 WLAN (PCIe Gen3 x1+ Intel CNVi)

NOTE: The PCIe Gen 4 x16 slot is meant for HP qualified cards, configured or after market. HP does not provide warranty support for 3rd party cards.

Supported Interfaces

SATA

Integrated (4) Serial ATA interfaces (6Gb/s SATA).

Serial Attached SCSI

None **Integrated Graphics**

Intel® UHD Graphics 730 (on Core i5-12400/i3-12300/i3-12100) processors); Intel® UHD Graphics 770 (on Core i5/i7/i9 processors); Based on Unified Memory Architecture (UMA) - a region of system

memory is reserved and dedicated to the graphics display.

Support for Microsoft DirectX 12, OpenGL 4.6 and OpenCL 3.0 on Intel®

UHD Graphics 730/770:

Based on Unified Memory Architecture (UMA) - a region of system memory is reserved and dedicated to the graphics display.

2 DP 1.4 graphics ports integrated in motherboard; Supports up to three

simultaneous displays across DisplayPort*/HDMI*/DVI outputs.

Max. resolution supported on onboard DP 1.4/HBR2 ports: 4096x2304 @

60Hz, 24bpp

Max. resolution supported on FlexIO DP 1.4/HBR3 port: 5120x3200

@60Hz, 24bpp

Network Controller Integrated Ethernet PHY Connection I219LM. Management capabilities:

WOL. PXE 2.1 and AMT 16

External SATA (eSATA) None **IDE** connector None Floppy connector None

Serial 1 internal header (requires optional Serial Port and PS/2 Combo Kit with

PCIe bracket)

2nd Serial 1 internal header (requires optional Serial Port Adapter Kit)

Front

2 Type-A SuperSpeed USB 10Gbps signaling rate port (charge supports up

to 5V/2.1A);

2 Type-A SuperSpeed USB 10Gbps signaling rate port; 1 Type-C[®] SuperSpeed USB 20Gbps signaling rate port (charge supports up to

5V/3A)

3 High-speed USB 480Mbps signaling rate port; 3 Type-A SuperSpeed USB Rear

5Gbps signaling rate port:

Flex I/O option:

1 SuperSpeed USB Type-C[®] 10Gbps signaling rate (Power Delivery 15W. Alt Mode DisplayPort); 1 Dual SuperSpeed USB Type-A 5Gbps signaling

Internal 1 High-speed USB 480Mbps signaling rate header for SD Card Reader

HD Integrated Audio

Flash ROM

Connector(s)

Yes

Realtek ALC3252

CPU Fan Header Yes Memory Fan Header None

Chassis Fan Header 1 Rear System Chassis Fan Header, 1 Graphic chassis Fan Header.

Front PCI Fan Header None

System Technical Specifications

Front Control Yes

Panel/Speaker Header

Yes

CMOS Battery Holder -Lithium

Integrated Trusted Integrated TPM 2.0 (Infineon SLB9672)

Platform Module Convertible to FIPS 140-2 Certified mode through firmware v15.21

Power Supply Headers Yes

Power Switch, Power LED Yes & Hard Drive LED Header

Clear Password Jumper None

Keyboard/Mouse USB or PS/2 Mouse (option)

Power Supply 260W EPA92, 450W EPA90 and 550W EPA92

¹Maximum memory capacities assume 64-bit operating systems, such as Genuine Windows® 10 Professional 64 bit, Red Hat Linux 64-bit. 32-bit Windows Operating Systems support up to 4 GB.

²M.2 storage supports compatible devices up to 80mm

PROCESSORS

Name	Ghz P- Core Base Frequenc y	Ghz E- Core Base Frequenc y	Core Max	Up to x GHz E-Core Max Turbo Frequency	L3 Cache (MB)	P- Core S	E- Core s	Total Cores	Processo r Threads	Memory Speed (MT/s) (DDR5) ⁴	ECC Memory Supporte d ⁵	Integrated Graphics	Featuring Intel® vPro® Technolog y³	TDP (W)	Max Turbo Freque ncy (GHz) ²
Intel 13 th Gene	ration Pro	ocessors													
Intel® Core™ i9-13900K	3	2.20	5.4	4.3	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i9-13900	2	1.50	5.2	4.2	36	8	16	24	32	5600	Y	Intel® UHD Graphics 770	Y	65	5.6
Intel® Core™ i7-13700K	3.4	2.50	5.3	4.2	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	125	5.8
Intel® Core™ i7-13700	2.1	1.50	5.1	4.10	30	8	8	16	24	5600	Y	Intel® UHD Graphics 770	Y	65	5.2
Intel® Core™ i5-13600K	3.5	2.60	5.1	3.9	24	6	8	14	20	5600	Y	Intel® UHD Graphics 770	Y	65	5.1
Intel® Core™ i5-13600	2.7	2.00	5.0	3.7	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	5.0
Intel® Core™ i5-13500	2.5	1.80	4.8	3.5	24	6	8	14	20	4800	Y	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-13400	2.5	1.80	4.6	3.3	20	6	4	10	16	4800	N	Intel® UHD Graphics 730	N/A	65	4.6
Intel 12 th Gene	eration Pro	ocessors													
Intel® Core™ i9-12900K	3.2	2.4	5.1	3.9	30	8	8	16	24	4800	Y	Intel® UHD Graphics 770	Y	125	5.2
Intel® Core™ i9-12900	5	1.8	5.0	3.8	30	8	8	16	24	4800	Y	Intel® UHD Graphics 770	Y	65	5.1
Intel® Core™ i7-12700K	3.6	2.7	4.9	3.8	25	8	4	12	20	4800	Y	Intel® UHD Graphics 770	Y	125	5.0



Intel® Core™ i7-12700	2.1	1.6	4.8	3.6	25	8	4	12	20	4800	Y	Intel® UHD Graphics 770	Y	65	4.9
Intel® Core™ i5-12600K	3.7	2.8	4.9	3.6	20	6	4	10	16	4800	Y	Intel® UHD Graphics 770	Υ	125	4.9
Intel® Core™ i5-12600	3.3	N/A	4.8	N/A	18	6	0	6	12	4800	Y	Intel® UHD Graphics 770	Y	65	4.8
Intel® Core™ i5-12500	3	N/A	4.6	N/A	18	6	0	6	12	4800	Y	Intel® UHD Graphics 770	Υ	65	4.6
Intel® Core™ i5- 12400	2.5	N/A	4.4	N/A	18	6	0	6	12	4800	N	Intel® UHD Graphics 730	N/A	65	4.4
Intel® Core™ i3-12300	3.5	N/A	4.4	N/A	12	4	0	4	8	4800	N	Intel® UHD Graphics 730	N/A	60	4.4
Intel® Core™ i3-12100	3.3	N/A	4.3	N/A	12	4	0	4	8	4800	N	Intel® UHD Graphics 730	N/A	60	4.3

¹ Multicore is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance.

³ Intel vPro® requires Windows 10 Pro 64 bit or higher, a vPro supported processor, vPro enabled chipset, vPro enabled wired LAN and/or Wi-Fi 6E WLAN and TPM 2.0. Some functionality requires additional 3rd party software in order to run. Features of vPro® Essentials and Enterprise vary. See http://intel.com/vpro

⁴ Memory will run at 4400 speed (MT/s) if there is one DIMM per channel. 2 DIMMS per channel will run 4000 speed (MT/s). DIMMs must be the same, either 8GB or 16GB DIMMs. 32GB DIMMs run at 3200 MT/s.

System Configurations

HP Z2 G9 SFF Workstation Processor Info
Desktop PC Configuration Memory Info
#1 Graphics Info

 Processor Info
 Core i5-12500,6C 3.0G 65W

 Memory Info
 2 x 8G DDR5 4800 UDIMM NECC

Graphics Info NVIDIA T400 4GB **Disks/Optical/Floppy** 512GB SSD Z Turbo

PSU 260W Other NA

Energy Consumption (Watts)

	115 VAC 230 VAC		VAC	100	VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
Windows long Idle (S0)	16.	16.907		16.195		452	
Windows short Idle (S0)	17.	323	17.	742	17.	245	
Windows Busy Typ(S0)	165	.717	168	.913	164	.628	
Windows Busy Max (S0)	187	.903	183.393		186	.965	
Sleep (S3)	1.001	0.991	1.033	1.001	0.991	1.033	
Off (S5)	0.657 0.631		0.672 0.657		0.631	0.672	
Zero Power Mode (ErP)	0.229		0.2	:37	0.224		

Heat Dissipation 115 VAC 230 VAC 100 VAC

² Intel Turbo Boost performance varies depending on hardware, software and overall system configuration. See http://www.intel.com/technology/turboboost for more information.

⁵ Error Correction Memory

(Btu/hr)

	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Enabled	LAN Enabled
Windows long Idle (S0)	57.0	687	55.257		56.134	
Windows short Idle (S0)	59.	59.106		536	58.84	
Windows Busy Typ(S0)	565.426		576.331		561.711	
Windows Busy Max (S0)	641.	.125	625	.737	637	.925
Sleep (S3)	3.415	3.381	3.525	3.415	3.381	3.525
Off (S5)	2.242	2.153	2.293	2.242	2.153	2.293
Zero Power Mode (ErP)	0.7	81	0.8	309	0.764	

HP Z2 G9 SFF Workstation
 Desktop PC Configuration
 #2
 Memory Info
 Graphics Info

 Processor Info
 Core i7-12700,12C 2.1G 65W

 Memory Info
 2 x 8G DDR5 4800 UDIMM NECC

Graphics Info NVIDIA T1000 8GB **Disks/Optical/Floppy** 512GB SSD Z Turbo

PSU 450W Other NA

Energy Consumption (Watts)

	115 VAC		230	VAC	100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	19.	136	19.335		19.	211
Windows short Idle (S0)	20.	404	21.197		20	.32
Windows Busy Typ(S0)	245	.533	239	.257	242.62	
Windows Busy Max (S0)	268	.903	247	.683	266	.482
Sleep (S3)	1.132	1.101	1.211	1.132	1.101	1.211
Off (S5)	0.735	0.722	0.744	0.735	0.722	0.744
Zero Power Mode (ErP)	0.2	:65	0.2	.68	0.7	252

Heat Dissipation (Btu/hr)

	115 VAC		230	VAC	100 VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Enabled	LAN Enabled	LAN Enabled	
Windows long Idle (S0)	65.	292	65.971		65.	548	
Windows short Idle (S0)	69.618		72.	324	69.332		
Windows Busy Typ(S0)	837	.759	816	.345	827	.819	
Windows Busy Max (S0)	917	.497	845	.094	909	.237	
Sleep (S3)	3.862	3.757	4.132	3.862	3.757	4.132	
Off (S5)	2.508	2.508 2.463		2.508	2.463	2.539	
Zero Power Mode (ErP)	0.9	04	0.9	14	0.	86	

HP Z2 G9 SFF Workstation Processor Info
Desktop PC Configuration Memory Info
#3 Graphics Info

 Processor Info
 Core i7-12700K,12C 3.6G 125W

 Memory Info
 2 x 16G DDR5 4800 UDIMM ECC

Graphics Info NVIDIA RTX A2000 **Disks/Optical/Floppy** 512GB SSD Z Turbo

PSU 450W Other NA

Energy Consumption (Watts)

	115 VAC		230	VAC	100 VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
Windows long Idle (S0)	21.	21.043		428	20.228		
Windows short Idle (S0)	23.125		22.638		22.444		
Windows Busy Typ(S0)	258.063		253.127		256.521		
Windows Busy Max (S0)	274.25		263.	.977	268.45		



System Technical Specifications

Sleep (S3)	1.302	1.221	1.411	1.302	1.221	1.411
Off (S5)	0.705	0.691	0.725	0.705	0.691	0.725
Zero Power Mode (ErP)	0.2	238	0.2	242	0.7	239

Heat Dissipation (Btu/hr)

	115 VAC		230	VAC	100 VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
Windows long Idle (S0)	71.	799	69.700		69.	018	
Windows short Idle (S0)	78.	903	77.241		76.	579	
Windows Busy Typ(S0)	880	.511	863.669		875.25		
Windows Busy Max (S0)	935	.741	900).69	915	.951	
Sleep (S3)	4.442	4.166	4.814	4.442	4.166	4.814	
Off (S5)	2.405	2.358	2.474	2.405	2.358	2.474	
Zero Power Mode (ErP)	0.8	312	0.0	326	0.815		

HP Z2 G9 SFF Workstation Processor Info
Desktop PC Configuration Memory Info
#4 Graphics Info

 Processor Info
 Core i7-12700K,12C 3.6G 125W

 Memory Info
 4 x 16G DDR5 4800 UDIMM NECC

Graphics Info NVIDIA RTX A2000 **Disks/Optical/Floppy** 1T SSD Z Turbo

PSU 550W Other NA

Energy Consumption (Watts)

	115 VAC		230 VAC		100 VAC		
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	
Windows long Idle (S0)	16.	118	16.	16.525		16.022	
Windows short Idle (S0)	17.591		17.935		17.485		
Windows Busy Typ(S0)	166.23		166.157		165.652		
Windows Busy Max (S0)	215.6		214.207		213	.633	
Sleep (S3)	1.023	0.968	1.215	1.023	0.968	1.215	
Off (S5)	0.654	0.642	0.678	0.654	0.642	0.678	
Zero Power Mode (ErP)	0.248		0.2	252	0.7	248	

Heat Dissipation (Btu/hr)

	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	54.	995	56.	383	54.	667
Windows short Idle (S0)	60.	020	61.	194	59.	659
Windows Busy Typ(S0)	567.177		566.928		565.205	
Windows Busy Max (S0)	735.627		730	.874	728	.916
Sleep (S3)	3.491	3.303	4.146	3.491	3.303	4.146
Off (S5)	2.231	2.191	2.313	2.231	2.191	2.313
Zero Power Mode (ErP)	0.846		0.	86	0.8	346

HP Z2 G9 SFF Workstation
Desktop PC Configuration
#5

Processor Info
Memory Info
Graphics Info

 Processor Info
 Core i9-12900K,16C 3.2G 125W

 Memory Info
 4 x 32G DDR5 4800 UDIMM ECC

Graphics Info NVIDIA RTX A4000 **Disks/Optical/Floppy** 1T SSD Z Turbo

PSU 550W Other NA

Energy Consumption (Watts)

115 VAC		230 VAC		100 VAC	
LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled



System Technical Specifications

Windows long Idle (S0)	32.725		32.709		32.711	
Windows short Idle (S0)	33.525		35.083		33.432	
Windows Busy Typ(S0)	392	.633	392	2.11	390	.621
Windows Busy Max (S0)	419	.361	406	.324	414	.845
Sleep (S3)	1.929	1.862	2.142	1.929	1.862	2.142
Off (S5)	0.776	0.749	0.825	0.776	0.749	0.825
Zero Power Mode (ErP)	0.213		0.2	219	0.7	208

Heat Dissipation (Btu/hr)

	115 VAC		230 VAC		100 VAC	
	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled	LAN Enabled	LAN Disabled
Windows long Idle (S0)	111.658		111.603		111.61	
Windows short Idle (S0)	114.387		119.703		114.07	
Windows Busy Typ(S0)	1339.664		1337.879		1332.799	
Windows Busy Max (S0)	1430.86		1386	5.377	141!	5.451
Sleep (S3)	6.582	6.353	7.309	6.582	6.353	7.309
Off (S5)	2.648	2.556	2.815	2.648	2.556	2.815
Zero Power Mode (ErP)	0.727		0.747		0.71	

NOTE: The Power Supply Efficiency report may be found at the following links: https://www.plugloadsolutions.com/80PlusPowerSuppliesDetail.aspx?id=0&type=2

Declared Noise Emissions

-,	Processor Info	Intel® CPU Core i5-12400 6C LGA 2.50G 18 MB 65W (Intel - Alder Lake-S)				
(Entry level, Lowprofile)	Memory Info	1* 32GB 4800 SK hynix memory				
	Graphics Info	Intel® UHD				
	Disks/Optical/Floppy	1*2TB Samsung M.2 LITE-ON 450W				
	Power Supply					
		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
	Idle	3.1	15.2			
	Hard drive Operating (Drive Random Seek)	3.4	23.9			
	Hard drive Operating (Active mode)	3.05	14.8			
System Configuration (Mid-level, Lowprofile)	Processor Info	Intel® CPU Core i9-12900 16C LGA 2.40G 30 MB 65W ECC (Intel - Alder Lake-S)				
	Memory Info	4* 32GB 4800 SK hynix memory				
	Graphics Info	NVIDIA® T1000	NVIDIA® T1000			
	Disks/Optical/Floppy	2*WD 2TB 7200RPM SATA HDD; 3*2T	B Samsung M.2			
	Power Supply	LITE-ON 450W				
Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
7779 and ISO 9296)	Idle	3.35	23.4			
	Hard drive Operating (Drive Random Seek)	3.48	24.9			

System Technical Specifications

	Hard drive Operating (Active mode)	4.34	30.5			
System Configuration (High-end, Lowprofile)	Processor Info	Intel® Core i9-12900K 16C 3.20G LGA S)	30 MB 125W ECC (Intel - Alder Lake-			
	Memory Info	4* 32GB 4800 SK hynix memory				
	Graphics Info	NVIDIA® T1000				
	Disks/Optical/Floppy	2*WD 2TB 7200RPM SATA HDD; 3*2TB Samsung M.2				
	Power Supply	LITE-ON 450W				
Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
	Idle	3.37	23.1			
	Hard drive Operating (Drive Random Seek)	3.45	24.7			
	Hard drive Operating (Active mode)	4.35	33.0			
System Configuration	Processor Info	Intel® Core i5-12400 6C LGA 2.50G 18 MB 65W (Intel - Alder Lake-S)				
(Entry level, Riser)	Memory Info	1* 32GB 4800 SK hynix memory				
	Graphics Info	Intel® UHD				
	Disks/Optical/Floppy	1*2TB Samsung M.2				
	Power Supply	Liteon 550W EPA92				
Declared Noise Emissions (in accordance with ISO		Sound Power (LWAd, bels)	Deskside Sound Pressure (LpAm, decibels)			
7779 and ISO 9296)	Idle	3.01	12.0			
	Hard drive Operating (Drive Random Seek)	3.37	23.1			
	Hard drive Operating (Active mode)	3.09	15.5			

Environmental
Requirements

Temperature Operating: 5° to 35° C (40° to 95° F)

Non-operating: -40° to 60° C (-40° to 140° F)

Maximum rate of change: 10°C/hr

Humidity Operating: 10% to 85% RH, non-condensing, 35° C maximum wet bulb

Non-operating: 10% to 90% RH, non-condensing, 35° C maximum wet bulb

Maximum Altitude Operating (with Rotational Hard Drives): 3,048 m (10,000 feet)

Operating (with only Solid-State Drives): 5,000 m (16,404 feet)

Non-operating: 12,192 m (40,000 feet)

Maximum operating temperature is reduced as altitude increases. See

Cooling for details.

Dynamic Shock

Operating: ½-sine: 40g, 2-3ms (~62 cm/sec) Non-operating: ½-sine: 160 cm/s, 2-3ms (~105g)

square: 422 cm/s, 20g

Vibration

Operating random: 0.5g (rms), 5-300 Hz, up to $0.0025g^2/Hz$ Non-operating random: 2.0g (rms), 5-500 Hz, up to $0.0150 g^2/Hz$



Cooling Above 1524 m (5,000 feet) altitude, the maximum operating temperature

is reduced by 1° C (1.8° F) for every 305 m (1,000 feet) increase in elevation,

up to 3048 m (10,000 feet)

NOTE: System enduring or operating beyond the environmental requirement

range is not recommended and may compromise system reliability

permanently.



System Technical Specifications

Physical Security and Serviceability

Access Panel Tool-less

Includes support information

Optical Drive Tool-less, except for Screw-In carrier **Hard Drives** Tool-less, except for internal/external bay

Expansion Cards Tool-less

Processor Socket Tool-less, except for the processor heatsink

Blue User Touch Points Yes, on tool-less internal chassis mechanisms

Color-coordinated Cables Yes

and Connectors

Memory Tool-less

System Board Screw-In

Padlock Support Yes (optional): Locks side cover and secures chassis from theft

0.22-in diameter padlock loop at rear of system

Cable Lock Support

Yes, Kensington Cable Lock (optional): Locks side cover and secures chassis from theft

3 mm x 7 mm slot at rear of system

Universal Chassis Clamp

Lock Support

Yes (optional): Locks side cover and locks cables to chassis. Secures chassis from theft and allows

multiple units to be chained together when used with optional cable

Threaded feature at rear of system

Solenoid Lock and Hood

Sensor

Yes (optional)

The Solenoid Hood Lock eliminates the need for a physical key by making the chassis lockable through

software and a password. You can also lock and unlock the chassis remotely over the network. The

Sensor Kit detects when the access panel has been removed.

Keyboard/Mouse/Video

Cable Lock

No

CPUs and Heatsinks A T-15 Torx or flat blade screwdriver is needed to remove the CPU heatsink before the CPU can be

removed. CPU removal is tool-less

Internal Speaker Yes

Power Supply Fans

70mm x 70mm x 25mm 4-wire PWM (non-serviceable)

Access Panel Key Lock

No No

Integrated Chassis

Handles

Power Supply Requires T15 Torx or flat blade screwdriver

PCI Card Retention Yes, rear (all), middle (optional), front (none)

Service, Support, and Warranty

On-site Warranty and Service¹: Three-years, limited warranty and service offering delivers on-site, next business-day² service for parts and labor and includes free telephone support³ 8am - 5pm. Global coverage² ensures that any product purchased in one country and transferred to another, non-restricted country will remain fully covered under the original warranty and service offering. 24/7 operation will not void the HP warranty. Storage devices are not covered under warranty for 24/7 operation except for Enterprise class HDDs.

NOTE 1: Terms and conditions may vary by country. Certain restrictions and exclusions apply.

NOTE 2: On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.

NOTE 3: Technical telephone support applies only to HP-configured, HP and HP-qualified, third-party hardware and software. Toll-free calling and 24x7 support service may not be available in some countries.

HP Care Pack Services extend service contracts beyond the standard warranties. Service starts from date of hardware purchase. To choose the right level of service for your HP product, use the HP Care Pack Services Lookup Tool at: http://www.hp.com/go/lookuptool. Service levels and response times for HP Care Packs may vary depending on your geographic location.

Certification and Compliance

Environmental Sustainability questions concerning:

- Ecolabels (EPEAT, TCO, etc.)
- ENERGY STAR, California Energy Commission (CEC)
- Compliance with Environmental legislation (EU ErP, China CECP, EU RoHS and other countries)
- Supply Chain Social Environmental Responsibility (SER) (conflict minerals; human rights, etc.)
- Product specific environmental features (material content, packaging content, recycled content, etc.)
- China Energy Label (CEL)

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Please contact sustainability@hp.com

For country specific Regulatory Compliance approval documents or Regulatory and Safety questions concerning:

- Declarations of Conformity (for self-service, go to https://www.hp.com/uk-en/certifications/technical/regulations-certificates.html?jumpid=ex_r135_uk/en/any/corp/hpuk-mu_chev/certificates)
- GS Certificates
- Product Safety Certificates (UL, CB, BIS, etc.)
- EMC Certificates, Declarations of Conformity, or Certificates of Conformity (CE, FCC, ICES, etc.)
- CCC Certificates
- Ergonomics

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Please contact techregshelp@hp.com

BIOS

BIOS 64-bit Services

BIOS supports 64-bit Operating systems only.

PCI 3.0 Support

Full BIOS support for PCI Express through industry standard interfaces.

ATAPI

ATAPI Removable Media Device BIOS Specification Version 1.0.

BBS

BIOS Boot Specification v1.01.(Not Support)

WMI Support

WMI is Microsoft's implementation of Web-Based Enterprise Management (WBEM) for Windows. WMI is fully compliant with the Distributed Management Task Force (DMTF) Common Information Model (CIM)

and WBEM specifications.

BIOS Boot Spec 1.01+

Provides more control over how and from what devices the workstation will boot.

BIOS Power On

Users can define a specific date and time for the system to power on.

ROM Based Computer Setup Utility (F10)

System/Emergency ROM Flash Recovery with

Video

SMBIOS

Recovers system BIOS in corrupted Flash ROM.

Replicated Setup

Saves BIOS settings to USB flash device in human readable file (HpSetup.txt).

Review and customize system configuration settings controlled by the BIOS.

BiosConfigurationUtility.exe utility can then replicate these settings on machines being deployed

without entering Computer Configuration Utility (F10 Setup). System Management BIOS Reference Specification, Version 3.4

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Boot Control Memory Change Alert

Thermal Alert

Disables the ability to boot from removable media on supported devices.

Alerts management console if memory is removed or changed. Monitors the temperature state within the chassis. Three modes:

• NORMAL - normal temperature ranges.

ALERTED - excessive temperatures are detected. Raises a flag so action can be taken to avoid

shutdown or provide for a smoother system shutdown.

• SHUTDOWN - excessive temperatures are encountered. Automatically shuts down the computer

without warning before hardware component damage occurs.

Remote ROM Flash **ACPI (Advanced**

Provides secure, fail-safe ROM image management from a central network console.

Configuration and Power

Allows the system to enter and resume from low power modes (sleep states).

Management Interface)

Enables an operating system to control system power consumption based on the dynamic workload. Makes it possible to place individual cards and peripherals in a low-power or powered-off state without

affecting other elements of the system.

Supports ACPI 6.0 for full compatibility with 64-bit operating systems.

Ownership Tag

A user-defined string stored in non-volatile memory that is displayed in the BIOS splash screen.

Shutdown

Remote Wakeup/Remote

System administrators can power on, restart, and power off a client computer from a remote location.

Instantly Available PC (Suspend to RAM - ACPI sleep state S3)

Allows for very low power consumption with quick resume time.

Remote System

Installation via F12 (PXE

2.1) (Remote Boot from

Allows a new or existing system to boot over the network and download software, including the operating system.

ROM revision levels

Reports the system BIOS revision level in Computer Configuration Utility (F10 Setup). Version is available through an industry standard interface (SMBIOS and WMI) so that management SW

applications can use and report this information.

System board revision

level

Server)

Allows management SW to read revision level of the system board. Revision level is digitally encoded into the HW and cannot be modified.

Start-up Diagnostics (Power-on Self-Test)

Assesses system health at boot time with selectable levels of testing.



Auto Setup when new

hardware installed System automatically detects addition of new hardware.

Keyboard-less Operation The system can be booted without a keyboard.

Localized ROM Setup Common BIOS image supports System Configuration Utility (F10 Setup) menus in 14 languages with

local keyboard mappings.

Asset Tag The user or MIS to set a unique tag string in non-volatile memory.

Allows I/O slot parameters (option ROM enable/disable, bus latency) to be configured individually. **Per-slot Control Adaptive Cooling** Control parameters are set according to detected hardware configuration for optimal acoustics.

(Pre-video) critical errors are reported via beeps and blinks on the power LED.

Pre-boot Diagnostics

UEFI Specification

Revision

2.7

ACPI Advanced Configuration and Power Management Interface, Version 6.0 ATA (IDE) AT Attachment 6 with Packet Interface (ATA/ATAPI-6). Revision 3b **CD Boot** "El Torito" Bootable CD-ROM Format Specification Version 1.0

EDD Enhanced Disk Drive Specification Version 1.1

BIOS Enhanced Disk Drive Specification Version 3.0(Not support)

EHCI Enhanced Host Controller Interface for Universal Serial Bus. Revision 1.0

PCI PCI Local Bus Specification, Revision 2.3

> PCI Power Management Specification, Revision 1.1 PCI Firmware Specification, Revision 3.0, Draft .7

PCI Express Base Specification, Revision 2.0 **PCI Express**

PCI Express Base Specification, Revision 3.0 PCI Express Base Specification, Revision 4.0

POST Memory Manager Specification, Version 1.01 (Not support) **PMM**

SATA Serial ATA Specification, Revision 1.0a

> Serial ATA 3 Gb/s: Serial ATA Specification, Revision 2.5 Serial ATA 6 Gb/s: Serial ATA Specification, Revision 3.0

SPD JEDEC JESD300-5

TPM Trusted Computing Group TPM Specification Version 2.0 (Infineon SLB 9670).

Common Criteria EAL4+ certified.

FIPS 140-2 Certification TCG TPM Certified products list:

http://www.trustedcomputinggroup.org/certification/tpm-certified-products/

UHCI Universal Host Controller Interface Design Guide, Revision 1.1

Universal Serial Bus Revision 1.1 Specification **USB**

Universal Serial Bus Revision 2.0 Specification Universal Serial Bus Revision 3.1 Specification

System Management BIOS Reference Specification, Version 3.2 **SMBIOS**

External BIOS simulator found at: http://csrsml.itcs.hp.com/

Social and Environmental Responsibility

& Declarations

Eco-Label Certifications This product is low halogen except for HP Z Turbo Quad Pro PCIe TLC SSD, CRU QX 428 and QX448 removable storage frames, ConnectX-6 DX Amphenol 10 & 25 Gb Transceivers, power cords, cables, and peripherals. Service parts obtained after purchase may not be Low Halogen.

> This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:

- IT ECO declaration
- **US ENERGY STAR®**
- US Federal Energy Management Program (FEMP)



System Technical Specifications

- EPEAT[®] Gold registered in the United States. See http://www.epeat.net for registration status in your country.
- TCO Certified
- China Energy Conservation Program (CECP)
- China State Environmental Protection Administration (SEPA)
- Taiwan Green Mark
- Korea Eco-label
- Japan PC Green label*

Sustainable Impact Specifications

- Product Carbon Footprint (hp.com)
- Ocean-bound plastic in System FAN, CPU FAN and Speaker
- 45% post-consumer recycled Plastic
- Low halogen
- Outside Box and corrugated cushions are 100% sustainably sourced and recyclable
- Molded Paper Pulp Cushion inside box is 100% sustainably sourced and recyclable
- Bulk packaging available

System Configuration

The configuration used for the Energy Consumption and Declared Noise Emissions data for the Notebook model is based on a "Typically Configured Notebook".

Energy Consumption (in accordance with US ENERGY STAR® test method)

method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Sort idle)	45.62 W	45.60 W	45.63 W
Normal Operation (Long idle)	41.46 W	41.62 W	41.57 W
Sleep	2.34 W	2.34 W	2.39 W
Off	0.89 W	0.91 W	0.90 W

NOTE:

Energy efficiency data listed is for an ENERGY STAR® compliant product if offered within the model family . HP computers marked with the ENERGY STAR® Logo are compliant with the applicable U.S. Environmental Protection Agency (EPA) ENERGY STAR® specifications for computers. If a model family does not offer ENERGY STAR® compliant configurations, then energy efficiency data listed is for a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.

Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz
Normal Operation (Short idle)	156 BTU/hr	156 BTU/hr	156.1 BTU/hr
Normal Operation (Long idle)	141.8 BTU/hr	142.3 BTU/hr	142.2 BTU/hr
Sleep	8 BTU/hr	8 BTU/hr	8.2 BTU/hr
Off	3 BTU/hr	3.1 BTU/hr	3.1 BTU/hr

*NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour.

Declared Noise Emissions (in accordance wit

(in accordance withSound PowerSound PressureISO 7779 and ISO 9296)(Lwad, bels)(LpAm, decibels)



Typically Configured – Idle	3.37	23.1
Fixed Disk – Random writes	3.45	24.7
Optical Drive – Sequential	4.35	33.0

Longevity and Upgrading

This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the

Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.

Additional Information

- This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive
 2011/65/EC.
- This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.
- This product is in compliance with California Proposition 65 (State of California; Safe Drinking Water and Toxic Enforcement Act of 1986).
- This product is in compliance with the IEEE 1680 (EPEAT) standard at the Gold level, see www.epeat.net
- Plastics parts weighing over 25 grams used in the product are marked per ISO11469 and ISO1043.
- This product is 93.5% recycle-able when properly disposed of at end of life.

Packaging Materials

External:	PAPER/Corrugated	1204 g
	PAPER/Molded Pulp	722 g
Internal:	PLASTIC/Polyethylene low density - LDPE	40 g

The plastic packaging material contains at least 0.0% recycled content.

The corrugated paper packaging materials contains at least 35% recycled content.

RoHS Compliance

HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.

We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.

We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.

To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS position statement.

Material Usage

This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at

http://www.hp.com/hpinfo/globalcitizenship/environment/supplychain/gen_specifications.html):

- Asbestos
- Certain Azo Colorants
- Certain Brominated Flame Retardants may not be used as flame retardants in plastics



- Cadmium
- Chlorinated Hydrocarbons
- Chlorinated Paraffins
- Bis(2-Ethylhexyl) phthalate (DEHP)
- Benzyl butyl phthalate (BBP)
- Dibutyl phthalate (DBP)
- Diisobutyl phthalate (DIBP)
- Formaldehyde
- Halogenated Diphenyl Methanes
- Lead carbonates and sulfates
- Lead and Lead compounds
- Mercuric Oxide Batteries
- Nickel finishes must not be used on the external surface designed to be frequently handled or carried by the user.
- Ozone Depleting Substances
- Polybrominated Biphenyls (PBBs)
- Polybrominated Biphenyl Ethers (PBBEs)
- Polybrominated Biphenyl Oxides (PBBOs)
- Polychlorinated Biphenyl (PCB)
- Polychlorinated Terphenyls (PCT)
- Polyvinyl Chloride (PVC) except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
- Radioactive Substances
- Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)

Packaging Usage

HP follows these guidelines to decrease the environmental impact of product packaging:

- Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
- Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
- Design packaging materials for ease of disassembly.
- Maximize the use of post-consumer recycled content materials in packaging materials.
- Use readily recyclable packaging materials such as paper and corrugated materials.
- Reduce size and weight of packages to improve transportation fuel efficiency.
- Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.

End-of-life Management and Recycling

HP offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.

The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.



System Technical Specifications

HP, Inc. Corporate Environmental Information For more information about HP's commitment to the environment:

Global Citizenship Report

http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html

Eco-label certifications

http://www8.hp.com/us/en/hp-information/environment/ecolabels.html

ISO 14001 certificates:

http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842

http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

footnotes

- Percentage of ocean-bound plastic contained in each component varies by product
- Recycled plastic content percentage is based on the definition set in the IEEE 1680.1-2018 standard.
- External power supplies, WWAN modules, power cords, cables and peripherals excluded.
- 100% outer box packaging and corrugated cushions made from sustainably sourced certified and recycled fibers.
- Fiber cushions made from 100% recycled wood fiber and organic materials.



Technical Specifications - Hard Drives

SATA	Hard	Drives	for HP	
Workstations				

500GB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity 500GB
Protocol SATA
Form Factor 3.5"
Controller AHCI

Height 1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm

Up to 600MB/s *

Physical Size 4 in; 10.17 cm

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

32MB

Seek Time (typical reads,
includes controller
overhead, includingSingle Track
Average2 ms *11 ms *Full Stroke21 ms *

settling)

Buffer

Rotational Speed 7,200 rpm **Logical Blocks** 976,773,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB	SATA	7200	rpm
6Gb	/s 3.5	" HDD	_

Capacity	1TB
Protocol	SATA
Form Factor	3.5"
Controller	AHCI
Height	1 in; 2.54 cm

Width Media Diameter 3.5 in; 8.9 cm
Physical Size 4 in; 10.17 cm

Up to 600 MB/s *

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Seek Time (typical reads, includes controller overhead, including settling)

Single Track 2 ms *

Average 11 ms *

Full Stroke 21 ms *

Rotational Speed 7,200 rpm Logical Blocks 1,953,525,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

2TB SATA 7200 rpm 6Gb/s 3.5" HDD Capacity2TBProtocolSATAForm Factor3.5"ControllerAHCI



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

Annualized Failure Rate

(based on Rated POH) < 0.62% Height 1 in; 2.54 cm

Width **Media Diameter** 3.5 in: 8.9 cm **Physical Size** 4 in: 10.17 cm

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

Up to 600MB/s *

Buffer 64MB

Seek Time (typical reads, **Single Track** 2.0 ms * includes controller Average 11 ms * overhead, including **Full Stroke** 21 ms * settling)

Rotational Speed 7,200 rpm **Logical Blocks** 3,907,029,168

Operating Temperature 41° to 131° F (5° to 55° C)

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

Capacity 1TB Height 1 in; 2.54 cm **Protocol** SATA **Form Factor** 3.5" **Controller AHCI** Reliability 2.0M hours **Rated Power On Hours** 8760/vr

Annualized Failure Rate

(based on Rated POH) <0.62%

Width **Media Diameter** 3.5 in: 8.9 cm **Physical Size** 4 in; 10.17 cm

Up to 600MB/s *

Interface Serial ATA (6.0 Gb/s), NCQ Enabled

Synchronous Transfer

Rate (Maximum)

128MB

Buffer

Seek Time (typical reads. Single Track 0.32ms* includes controller **Average** 7.45ms* overhead, including **Full Stroke** 14.2ms* settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s*

Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

> Capacity 2TB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Protocol SATA **Form Factor** 3.5" **Controller** AHCI Reliability (MTBF) 2.0M hours **Rated Power On Hours** 8760/yr **Annualized Failure Rate** < 0.62%

(based on Rated POH) Rated for 24/7/365

Operation

Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in: 10.17 cm

Media Diameter 3.5 in: 8.9 cm Interface Serial ATA (6Gb/s), NCQ enabled

Synchronous Transfer Up to 600MB/s*

Rate (Maximum)

128MB

Seek Time (typical reads, **Single Track** 0.7ms* includes controller Average 8.5ms* overhead, including **Full Stroke** 15.7ms* settling)

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s* **Sequential Write**

up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

4TB SATA 7200 rpm 6Gb/s 3.5" HDD (Enterprise Class)

2TB SATA 7200 rpm

6Gb/s 3.5" HDD

(Enterprise Class)

Capacity 4TB SATA Protocol **Form Factor** 3.5" Controller AHCI Reliability 2.0M hours 8760/yr **Rated Power On Hours** Annualized Failure Rate <0.62%

(based on Rated POH) Rated for 24/7/365

Operation

Physical Size (Height) 1 in; 2.54 cm Physical Size (Width) 4 in; 10.17 cm **Media Diameter** 3.5 in; 8.9 cm **Physical Size** 4 in; 10.17 cm

Interface Serial ATA (6Gb/s), NCQ enabled

Up to 600MB/s*

Synchronous Transfer

Rate (Maximum)

Buffer

256MB

^{*}Actual performance may vary.

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average0.7ms*Average
Full Stroke8.5ms*15.7ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 131° F (5° to 55° C)

Performance Sequential Read up to 226MB/s*
Sequential Write up to 226MB/s*

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

8TB SATA 7200 rpm
6Gb/s 3.5" HDD
(Enterprise Class)

Capacity	8TB
Protocol	SATA
Form Factor	3.5"
Controller	AHCI
Reliability	2.0M hours

WidthMedia Diameter3.5 in; 8.9 cmPhysical Size4 in; 10.17 cm

Up to 600MB/s [1]

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 256MB

Seek Time (typical reads,
includes controller
overhead, including
settling)Single Track
Average
Full Stroke0.7ms*
8.5ms*Full Stroke15.7ms*

Rotational Speed 7,200 rpm

Operating Temperature 41° to 140° F (5° to 60° C)

Performance Sequential Read up to 226MB/s¹
Sequential Write up to 226MB/s¹

Enterprise Class Features High Reliability

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

500GB SATA 7.	2K SED
2.5" HDD	

Capacity	500GB	
Protocol	SATA	
Form Factor	2.5"	

Height 0.275 in; 0.7 cm

Width Media Diameter 2.5 in; 6.36 cm
Physical Size 2.75 in; 6.99 cm

Up to 600MB/s*

Interface Serial ATA (6.0Gb/s), NCQ enabled

Synchronous Transfer

Rate (Maximum)

Buffer 64MB

Single Track 1ms*



^{*}Actual performance may vary.

^{*}Actual performance may vary.

25ms (Typical)*

Technical Specifications - Hard Drives

Seek Time (typical reads, Average 4.2ms*

includes controller Full Stroke overhead, including

settling)

Rotational Speed 7,200 rpm

Operating Temperature 32° to 131° F (0° to 60° C)

Self-Encrypting Drive Yes

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity 512GB TLC PCIe SSD Protocol (Z2G9) _ _ _

Capacity512GBProtocolPCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability (MTBF) 1.5M hours

InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s*

Sequential Write 3400MB/s*
Random Read 600K IOPS*
Random Write 600K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity
1TB TLC PCIe SSD (Z2G9) Protocol

Capacity 1TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

Capacity 2TB



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 500TBW (TB Written)

HP Z Turbo Drv PCIE-4X4 Reliability 2TB TLC PCIe SSD (Z2G9) Interface

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

1.5M Hours

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE-4X4 Capacity

4TB

TLC PCIe SSD

Capacity 4TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 600TBW (TB Written)

Reliability (MTBF) 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 700K IOPS*
Random Write 700K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv PCIE Gen4x4 4TB

TLC PCIe SED OPAL2

Capacity 4TB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance600TBW (TB Written)InterfacePCI Express 4.0 x4 electricalOperating Temperature32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 700K IOPS*
Random Write 700K IOPS*

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Self-Encrypting Drive

OPAL2

Support

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 512GB TLC PCIe SED OPAL2 (Z2G9)

512GB Capacity **Protocol** PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe **NAND Type** 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

PCI Express 4.0 x4 electrical Interface **Operating Temperature** 32° to 178° F (0° to 81° C)

Performance Sequential Read 6400MB/s* Sequential Write 3400MB/s*

Random Read 600K IOPS* Random Write 600K IOPS*

Self-Encrypting Drive OPAL₂

Support

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 1TB
TLC PCIe SED
OPAL 2 (72G9)

Capacity 1TB **Protocol** PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe **NAND Type** 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical **Operating Temperature** 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

> Sequential Write 5000MB/s* **Random Read** 800K IOPS* **Random Write** 800K IOPS*

Self-Encrypting Drive

Support

OPAL2

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

HP Z Turbo Drv 2TB TLC PCIe SED OPAL2 (Z2G9)

Capacity 2TB **PCIe Protocol**

Form Factor M.2 in native Slot on motherboard

^{*}Actual performance may vary.

^{*}Actual performance may vary.

Controller NVMe NAND Type 3D TLC

Endurance 500TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 178° F (0° to 81° C)

Performance Sequential Read 6500MB/s*

Sequential Write 5000MB/s*
Random Read 800K IOPS*
Random Write 800K IOPS*

Self-Encrypting Drive OPAL2

Support

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

256GB 2280 PCIe-4x4 Value M.2 SSD Capacity 256GB Protocol PCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe
NAND Type 3D TLC

Endurance 150TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical
Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3100MB/s*

Sequential Write 1400MB/s*
Random Read 200K IOPS*
Random Write 400K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

512GB 2280 PCIe-4x4 Value M.2 SSD Capacity 512GB Protocol PCle

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 300TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 380K IOPS*
Random Write 430K IOPS*



^{*}Actual performance may vary.

^{*}Actual performance may vary.

Technical Specifications - Hard Drives

*Actual performance may vary.

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.

1TB 2280 PCIe-4x4 ValueCapacity1TBM.2 SSDProtocolPCIe

Form Factor M.2 in native Slot on motherboard

Controller NVMe NAND Type 3D TLC

Endurance 400TBW (TB Written)

Reliability 1.5M Hours

Interface PCI Express 4.0 x4 electrical Operating Temperature 32° to 158° F (0° to 70° C)

Performance Sequential Read 3400MB/s*

Sequential Write 2500MB/s*
Random Read 500K IOPS*
Random Write 440K IOPS*

NOTE: For storage drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36GB of system disk (for Windows) is reserved for system recovery software.



^{*}Actual performance may vary.

Technical Specifications - Graphics

AMD Radeon™ Pro W6600 8GB Graphics Form Factor Single slot, full-height, 9.5" length

Graphics Controller Navi23 architecture
Power: 122 Watts

Cooling Solution: Active Fan Heatsink

Bus Type PCI Express 4.0 x8

Memory 8GB GDDR6 Memory
Memory Bandwidth: 224 GB/s

Memory Interface: 128 bit

Connectors 4x DisplayPort™ 1.4 with DSC

- HDR Ready

- Supports Multi-Stream Transport (MST)

Max simultaneous

displays

@ 60Hz with HDR Enabled 4x @ 3840x2160px (4K) 4x @ 5120x2880px (5K) 1x @ 7680x4320px (8K)

Shading Architecture

Supported Graphics APIs

DirectX 12 Shader Model 6.5 DirectX®12 Ultimate

OpenGL® 4.6 OpenCL™ 2.1 Vulkan™ 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T400 2GB Graphics **Form Factor** Single Slot, Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture

Max Power: 30 Watts

Cooling Solution: Active fan heatsink

Bus TypePCI Express 3.0 x16Memory2GB GDDR6 Memory

Memory Bandwidth: 80 GB/s Memory Interface: 64 bit

Connectors 3x mDP (Mini DisplayPort™) 1.4 Connectors

 Max simultaneous
 - 3x 3840 x 2160 @ 120Hz

 displays
 - 3x 5120 x 2880 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture Direct X 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA. OpenCL 1.2

Available Graphics Windows 10 64-bit Windows 11 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

Technical Specifications - Graphics

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T400 4GB Graphics

Form Factor Single Slot. Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture

Max Power: 30 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 4GB GDDR6 Memory Memory

> Memory Bandwidth: 80 GB/s Memory Interface: 64 bit

Connectors 3x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays - 3x 3840 x 2160 @ 120Hz

- 3x 5120 x 2880 @ 60Hz

DirectX 12 Shader Model 5.1

- supports Multi-Stream Transport (MST)

Shading Architecture

Supported Graphics APIs OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux[®] 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T600 4GB Graphics

Form Factor Single Slot, Low Profile (2.7" H x 6.1" L)

Graphics Controller Turing architecture

Max Power: 40 Watts

Cooling Solution: Active fan heatsink

Bus Type PCI Express 3.0 x16 Memory 4GB GDDR6 Memory

> Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors 4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays - 4x 5120 x 2880 @ 60Hz

- 2x 7680 x 4320 @ 60Hz

- 4x 3840 x 2160 @ 120Hz

supports Multi-Stream Transport (MST)

Shading Architecture

DirectX 12 Shader Model 5.1

Supported Graphics APIs OpenGL 4.6 DirectX 12 Vulkan 1.2



Technical Specifications - Graphics

API support includes:

CUDA, OpenCL 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 4GB Graphics Form Factor

Single Slot, Low Profile (2.7" H x

6.1" L)

Graphics Controller

Turing architecture Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type Memory PCI Express 3.0 x16 4GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors

4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays

- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz - 2x 7680 x 4320 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture

Supported Graphics APIs

DirectX 12 Shader Model 5.1 OpenGL 4.6

DirectX 12 Vulkan 1.2

API support includes: CUDA, OpenCL 1.2 Windows 10 64-bit

Available Graphics

Drivers

Windows 10 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® T1000 8GB Graphics

Form Factor

Single Slot, Low Profile (2.7" H x

6.1" L)

Graphics Controller

Turing architecture
Max Power: 50 Watts

Cooling Solution: Active fan heatsink

Bus Type Memory PCI Express 3.0 x16

8GB GDDR6 Memory

Memory Bandwidth: 160 GB/s Memory Interface: 128 bit

Connectors

4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous displays

- 4x 3840 x 2160 @ 120Hz - 4x 5120 x 2880 @ 60Hz

Technical Specifications - Graphics

- 2x 7680 x 4320 @ 60Hz

- supports Multi-Stream Transport (MST)

Shading Architecture

DirectX 12 Shader Model 5.1

Supported Graphics APIs

OpenGL 4.6 DirectX 12

Vulkan 1.2 API support includes:

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

CUDA, OpenCL 1.2

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

NVIDIA® RTX™ A2000 12GB Graphics

Form Factor

Low-Profile Double Slot (2.7" H x

6.1" L)

Graphics Controller

Ampere architecture Power: 70 Watts

Cooling: Active Fan Heatsink

Bus Type Memory

PCI Express 4.0 x16 12GB GDDR6 memory

Memory Bandwidth: 288 GB/s Memory Interface: 192 bit

Support Error-correcting code (ECC)

Connectors

4x mDP (Mini DisplayPort™) 1.4 Connectors

Max simultaneous

displays

4x 4096 x 2160 @ 120 Hz. 4x 5120 x 2880 @ 60 Hz 2x 7680 x 4320 @ 60 Hz

Shading Architecture

Supported Graphics APIs OpenGL 4.6

DirectX 12

Vulkan 1.2 API support includes:

Shader Model 6.5

CUDA, OpenCL 1.2

Available Graphics

Drivers

Windows 10 64-bit Windows 11 64-bit

Linux® 64-bit (selected Enterprise distributions)

HP qualified drivers may be preloaded or available from the HP support

Web site:

http://welcome.hp.com/country/us/en/support.html

HP 9.5mm Slim DVD Writer

Description

Interface Type

9.5mm height, tray-load

Mounting Orientation

Either horizontal or vertical SATA/ATAPI

Dimensions (WxHxD)

128 x 9.5 x 127mm

Supported Media Types

DVD+R

DVD+RW



Technical Specifications - Graphics

DVD+R DL DVD-R DL DVD-R DVD-RW CD-R CD-RW

Disc Capacity DVD-ROM 8.5 GB DL or 4.7 GB standard

Access Times Full Stroke DVD < 200 ms (seek) **Full Stroke CD** < 200 ms (seek)

CD-ROM, CD-R Up to 24X

Maximum Data Transfer CD ROM Read Rates CD-RW Up to 24X

DVD ROM Read DVD+RW Up to 8X

> DVD-RW Up to 8X DVD+R DL Up to 8X DVD-R DL Up to 8X DVD-ROM Up to 8X DVD-ROM DL Up to 8X DVD+R Up to 8X DVD-R Up to 8X

Power Source SATA DC power receptacle

> **DC Power Requirements** 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC -< 800 mA typical, <1600 mA maximum

10% to 80%

84° F (29° C)

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity Maximum Wet Bulb

Temperature

Operating Systems

Supported

Windows 10, Windows 7 Professional 32-bit and 64-bit,

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP

Home 32*. Linux®

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents HP SATA DVD Writer drive, installation guide.

USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport **Approvals**

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

HP 9.5mm Slim DVD-ROM Description

Drive

9.5mm height, tray-load **Mounting Orientation** Either horizontal or vertical

Interface Type SATA / ATAPI **Dimensions** (WxHxD) 128 x 9.5 x 127mm

Disc Capacity DVD-ROM Single layer: Up to 4.7 GB Double layer: Up to 8.5 GB

Technical Specifications - Graphics

Access Times DVD-ROM Single Layer < 110 me (typical)

CD-ROM Mode 1 < 110 ms (typical)
Full Stroke DVD < 230 ms (typical)
Full Stroke CD < 220 ms (typical)

Power Source SATA DC power receptacle

DC Power Requirements 5 VDC ± 5%-100 mV ripple p-p

DC Current 5 VDC – <800mA typical, < 1600 mA maximum

Operating Environmental Temperature 41° to 122° F (5° to 50° C)

(all conditions non-

condensing)

Relative Humidity 10% to 80% **Maximum Wet Bulb** 84° F (29° C)

Temperature

Operating Systems
Supported

Windows 10, Windows 7 Professional 32-bit and 64-bit,

Windows Vista Business 64*, Windows Vista Business 32*, Windows Vista Home Basic 32*, Windows 2000, Windows XP Professional or Windows XP

Home 32*. Linux®

No driver is required for this device. Native support is provided by the

operating system.

Kit Contents 9.5mm Slim DVD-ROM Drive, slim SATA data/power cable, installation

guide

Approvals USB-IF, WHQL, Compliant with USB Mass Storage Class Bulk only Transport

Specification Rev. 1.0,

Compliant Intel Front Panel I/O Connectivity Design Guide V. 1.3, FCC, CE,

BSMI, C-Tick, VCCI, MIC, cUL, TUVT

HP SD Media Card Reader Description USB3.0-SD4.0

NOTE: actual throughput is USB2.0.

Interface Type

• Support USB 2.0 LPM function

Support USB 3.0 U1/U2/U3 Power saving mode

Support USB 3.0 LTM function.

Dimensions (WxHxD)

Dedicated slot in front bezel (orderable option)

Supported Media Types

i. Secure Digital Card (SD)

ii. Secure Digital Support up to 2TB

iii. Secure Digital HC (SDHC)iv. Secure Digital XC (SDXC)

iv. Secure Digital AC (SDAC)

v. Support SD USH50 mode

vi. miniSD *1

vii. miniSDHC*1

viii. MicroSD*1

ix. MicroSDHC*1

x. MicroSDXC*1

NOTE: "*1" means Adapter Needed

Operating Systems Supported

No driver is required for this device. Native support is provided by the operating system.



Technical Specifications - Graphics

Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.microsoft.com.

See http://www.microsoft.com/windows/windows-7/ for details.



Technical Specifications - Networking and Communications

Integrated Intel® I219LM Connector

PCIe GbE Controller (Intel® vPro® with Intel® AMT 16.01) Connector RJ-45

Cabling Twisted pair up to 100m

Controller Intel® I219LM GbE platform LAN connect networking controller

Memory 3 KB Tx and 3KB Rx FIFO packet buffer memory

Data Rates Supported 10/100/1000 Mbps

Compliance 802.1as/1588, 802.1p, 802.1Q, 802.3, 802.3ab, 802.3az, 802.3i, 802.3u,

802.3z

Bus Architecture PCI Express and SMBus

Data Transfer Mode PCIe-based interface for active state operation (SO state) and SMBus for

host and management traffic (Sx low power state)

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps 100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

Management Capabilities vPro®, WOL, auto MDI crossover, PXE, Muti-port teaming, RSS, ACPI,

Advanced cable diagnostic, loopback modes,

AMT 16.0 support, Circuit Breaker, VLAN, Multicast Listener Discovery

(MLD)

¹Requires activation and a system with a corporate network connection, an Intel[®] AMT enabled chipset, and network hardware and software. For notebooks, Intel AMT may be unavailable or limited over a host OS-based VPN, when connecting wirelessly, on battery power, sleeping, hibernating, or powered off. Results dependent upon hardware, setup, and configuration. For more information, visit: https://www.intel.com/content/www/us/en/architecture-and-technology/intel-active-management-technology.html

HP 1-Port 1GbE Flex IO NIC

Connector RJ-45

Cabling 1GbE over Category 5e (or better) up to 100m

ControllerRealtek RTL8153Data Rates Supported10/100/1000 Mbps

Compliance 802.3 (LAN)

802.3u (100BASE-TX) 802.3ab (1000BASE-T) 802.3x (Ethernet Flow Control)

802.1Q (Virtual LAN)

802.3az (Energy Efficient Ethernet)

Bus Architecture USB

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Yes

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 10BASE-T (half-duplex) 10 Mbps

10BASE-T (full-duplex) 20 Mbps 100BASE-TX (half-duplex) 100 Mbps



Technical Specifications - Networking and Communications

100BASE-TX (full-duplex) 200 Mbps 1000BASE-T (full-duplex) 2000 Mbps

32° to 131° F (0° to 55° C) **Operating Temperature**

Dimensions (HxW) 1.5 in x 1.5 in. x 0.75 in (3.81 cm x 3.81 cm x 1.9 cm)

Operating System Driver Windows 11

Support

Windows 10 Linux®

Intel® X550-T2 2-Port **10GbE NIC**

Connector Dual-port RJ-45

Cabling 10GbE: Cat6a (or better) up to 100m

5GbE and below: Cat5e (or better) up to 100m

Controller Intel® Ethernet Controller X550 **Network Transfer Rates** 10GbE, 5GbE, 2.5GbE, 1GbE, 100MbE

Supported

Data Path Width PCIe Gen3x4

Power Requirement 11.2W (typical) 13.0 (Maximum) **Operating Temperature** 32° to 131° F (0° to 55° C)

Dimensions (HxW) 5.1 x 2.7 in (without brackets)

Operating System Driver Windows 11 64-Bit

Support

Windows 10 64-bit

Linux®

Kit Contents • Intel® X550-T2 2-Port 10GbE NIC with standard height bracket

attached

 Low-profile bracket Product Literature

NVIDIA Mellanox ConnectX-6 DX Dual Port 10/25GbE SFP28 NIC

Connector Dual-port SFP28

Cabling Transceiver with Multi-Mode Fiber OM3 or OM4)

Controller ConnectX-6 Dx **Network Transfer Rates** 1/10/25 GbE

Supported

Data Path Width PCIe Gen4x8

Power Requirement 19.74W Maximum power available through SFP28 port: 2.5W (each port)

Operating Temperature 32° to 131° F (0° to 55° C)

Dimensions (HxW) 6.22in. x 2.67in (158mm x 68mm)

Operating System Driver Windows 11 64-Bit

Windows 10 64-bit

Linux®

Kit Contents NVIDIA Mellanox ConnectX-6 SFP28 25GbE NIC with standard height

> bracket attached

· Low-profile bracket Product Literature

NOTE: The NVIDIA Mellanox ConnectX-6 DX network adapter requires either a PCIeG4 x4 or PCIeG4 x8 slot (electrical connection) to have full performance with two 25GbE SFP28 transceivers installed in the network adapter. When the network adapter is installed in a PCIeG3 x4 slot, the performance will

Technical Specifications - Networking and Communications

be limited when installing two 25GbE SFP28 transceivers or installing a 25GbE SFP28 transceiver plus a 10GbE SFP+ transceiver

NVIDIA Mellanox 25GbE SFP28 Transceiver

Operating Temperature
Operating Humidity
Dimensions (HxWxD)

Kit Contents

32°F to 158°F (0°C to 70°C) 5% to 85%, noncondensing 0.47 x 0.54 x 2.22 inches

NVIDIA Mellanox 25GbE SFP28 Transceiver

NVIDIA Mellanox 10GbE SFP+ SR Transceiver Operating Temperature
Operating Humidity
Dimensions (HxWxD)

Kit Contents

32°F to 158°F (0°C to 70°C) 5% to 85%, noncondensing 0.47 x 0.54 x 2.22 inches

NVIDIA Mellanox 10GbE SFP+ SR Transceiver

Intel® 1350-T4 4-Port 1GbE NIC Connector 4 RJ-45

CablingCat5e (or better) up to 100mControllerIntel® Ethernet I350 Controller

Network Transfer Rates

Supported

1GbE, 100MbE, 10MbE

Data Path Width PCle Gen2.1x4 **Power Requirement** 5W (typical)

Operating Temperature 32° to 131° F (0° to 55° C)

Dimensions (HxW) 2.75 x 5.5 inches (without brackets)

Operating System Driver

Support

Windows 11 Windows 10 Linux®

Kit Contents

Intel® I350-T4 4-Port 1GbE NIC with standard height bracket attached

Low-profile bracketProduct Literature

HP Flex 1GbE Fiber LC Single Port

Connector Fiber

Cabling 1GbE over Category OM1 (or better) up to 100m

ControllerMicrochip LAN7801Data Rates Supported100/1000 Mbps

Compliance IEEE 802.1p priority encoding/tagging (QoS, CoS)

IEEE 802.1q VLAN tagging IEEE 802.3x flow control

Bus Architecture USB

Power Requirement Requires 3.3V (integrated regulators for core Vdc)

Boot ROM Support Ye

Network Transfer Mode Full-duplex; Half-duplex

Network Transfer Rate 100BASE-X (half-duplex) 100 Mbps

1000BASE-X (half-duplex) 1000 Mbps 1000BASE-X (full-duplex) 2000 Mbps



Technical Specifications - Networking and Communications

Operating Temperature 32° to 158° F (0°C to 70°C)

1.5 in x 1.7 in. x 0.75 in (3.84 cm x 4.3 cm x 1.9 cm)

Operating System Driver Windows 11 64-Bit

Support

Windows 10 64-bit

Linux®

Intel® I225-T1 1-Port 2.5GbE NIC

Connector **RJ-45**

Cabling Cat5e (or better) up to 85m Controller Intel® Ethernet I225 Controller **Network Transfer Rates** 2.5GbE, 1GbE, 100MbE, 10MbE

Supported

Data Path Width PCIe Gen3.1x1 **Power Requirement** 1.9W (typical)

Operating Temperature 32° to 158° F (0°C to 70°C)

Dimensions (HxW) 2.7 in x 2.57 in. (68.7mm x 65.3mm)

Operating System Driver Windows 11 64-Bit

Windows 10 64-bit

Linux®

Kit Contents • Intel® I225-T1 1-Port 2.5GbE NIC with standard height bracket attached

> Low-profile bracket Product Literature

Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 **With Internal Antenna**

WLAN Standards 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2

High performance, low power dual band Pre-Standard-802.11ax R2 2x2.

both with 160MHz channel support - Wi-Fi 6E

2x2 Dual-Band (internal) **Antenna**

Bluetooth Standards 5.2

Operating Temperature 32° to 176° F (0° to 80° C)

Interface M.2 CNVio2 **Dimensions** M.2 2230

NOTE: The AX211 with internal antenna only support WIFI 6

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available

in countries where Wi-Fi 6E is supported.

Technical Specifications - Networking and Communications

Intel® Wi-Fi 6E* AX211 802.11ax, BT 5.3, M.2 With External Antenna WLAN Standards 802.11abgn+acR2+axR2(Pre-Standard) MIMO 2x2

High performance, low power dual band Pre-Standard-802.11ax R2 2x2,

both with 160MHz channel support - Wi-Fi 6E

Antenna 2x2 Dual- Band (External)

Bluetooth Standards 5.2

Operating Temperature 32° to 176° F (0° to 80° C)

InterfaceM.2 CNVio2DimensionsM.2 2230

NOTE: The AX211 with external antenna support WIFI 6E

*Wi-Fi 6E requires a Wi-Fi 6E router, sold separately, to function in the 6GHz band. Availability of public wireless access points limited. Wi-Fi 6E is backwards compatible with prior 802.11 specs. And available

in countries where Wi-Fi 6E is supported.

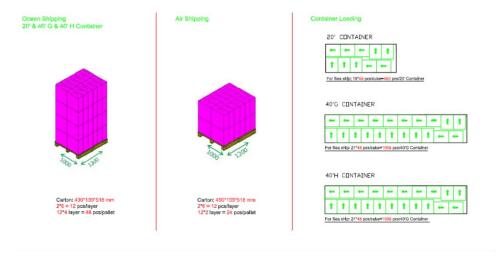


Technical Specifications - Palletization

Palletization

Ocean Shipping uses a 20' x 40' x 40' container (490mm x 199mm x 516mm) with 4 layers; 2x6=12 pieces per layer for a total of 48 pieces per pallet

Air shipping uses 490mm x 199mm x 516mm carton with 2 layers; 2x6=12 pieces per layer for a total of 24 pieces per pallet.





Summary of Changes

Date of change:	Version History:		Description of change:
March 8, 2022	From v1 to v2	Changed	Format
March 16, 2022	From v2 to v3	Changed	Social and Environmental Responsibility section
May 6, 2022	From v3 to v4	Changed	Processors, Graphics, Networking and Communications sections
May 19, 2022	From v4 to v5	Changed	Overview section in Packaged Dimensions subsection
June 1, 2022	From v5 to v6	Changed	Operating Systems and SATA Hard Drives sections
June 15, 2022	From v6 to v7	Changed	Networking and Communications section
July 1, 2022	From v7 to v8	Changed	Declared Noise Emissions section
August 1, 2022	From v8 to v9	Changed	Format pages 1-3, Overview section and Supported Components
August 4, 2022	From v9 to v10	Changed	Format
September 1, 2022	From v10 to v11	Changed	Graphics, Optical and Removable Storage Networking and Communications sections
October 1, 2022	From v11 to v12	Changed	Graphics, Networking and Communications sections
December 12, 2022	From v12 to v13	Changed	Format page 3
January 1, 2023	From v13 to v14	Changed	Networking and Communications section
February 1, 2023	From v14 to v15	Added	AMD Radeon Pro WX 3200 4GB (4)mDP GFX, w/2 mDP-to-DP adapters to Graphics section
March 1, 2023	From v15 to v16	Changed	Manageability section
March 30, 2023	From v16 to v17	Changed	Processors section
April 1, 2023	From v17 to v18	Changed	Networking and Communications section
April 25, 2023	From v18 to v19	Changed	Social and Environmental Responsibility section
May 1, 2023	From v19 to v20	Changed	Miscellaneous section
June 1, 2023	From v20 to v21	Changed	Graphics, Social and Environmental Responsibility, Palletization sections
July 1, 2023	From v21 to v22	Changed	Networking and Communications, Other Hardware, HP BIOS sections
July 5, 2023	From v22 to v23	Changed	ENVIRONMENTAL DATA section
August 1, 2023	From v23 to v24	Changed	Social and Environmental Responsibility section
August 1, 2023	From v24 to v25	Changed	ENVIRONMENTAL DATA section
October 1, 2023	From v25 to v26	Changed	Graphics, Input Devices sections



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